



Le79128-SW

LineCare[™] Software Package Next Generation Carrier Chipset (NGCC)

SOFTWARE PACKAGES

- Call Control Package
 - Call Control Functions
- Basic Test Package
 - Call Control Functions
 - GR909 Equivalent Line Testing
- Advanced Test Package
 - Call Control Functions
 - GR844 Equivalent Line Testing
- Advanced Test Plus Package
 - Call Control Functions
 - GR844 Equivalent Line Testing
 - Increased Accuracies, Additional Tests

BENEFITS

- Most cost-effective, highly-integrated, highly-featured line interface solution for plug and play analog line cards in self contained architectures and worldwide applications.
- Detailed 128 Channel RoHS compliant reference schematics available.
- Complete, all encompassing line testing solution for applications requiring comprehensive, multi-line analog line card functionality.
- Field-Upgradable Firmware for expanding line card test, control and signal processing capabilities.
- The NGVCP reduces the processing duties of the Host Processor. Tasks such as the line testing and cadencing are performed by the NGVCP, leaving the host more processor cycles for more complex applications or allowing the host to be a lower performance processor.
- Simplified programming interface as well as a sample quick start application to reduce development cycle and speed time to market.
- Self-diagnostics simplify production & system testing for lower cost of ownership.
- Fully validated test routines with published accuracies.

ORDERING INFORMATION

Software Package	Description
Le79128SLNT	Call Control
Le79128SLBT	Basic Test
Le79128SLAT	Advanced Test
Le79128SLATP	Advanced Test Plus

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DESCRIPTION

Microsemi's LineCareTM software package for the Next Generation VoiceEdgeTM Control Processor (NGVCP) is a complete software solution that aggregates control of Microsemi's Voice Termination Devices (VTDs) to provide a simplified programming interface.

The software package provides a set of functions additional to the feature set of the underlying VTDs. It significantly reduces the product development cycle and time-to-market. This document describes the software package for the NGVCP and the Next Generation Carrier Chipset (NGCC) devices. In combination, this set of devices provides a cost-effective, highly integrated and fully programmable line testing solution for applications requiring complete line card functionality.

Four different software packages are available:

- (1) Call Control (NT) package, implements all supported call control features.
- (2) Basic Test (BT) package, includes all the features of the NT package plus GR909 equivalent line test capabilities.
- (3) Advanced Test (AT) package, includes all the features of the BT package plus GR844 equivalent line test capabilities.
- (4) Advanced Test Plus (ATP) package, includes all the features of the AT package plus additional diagnostic tests and a line calibration feature for increased accuracies.

Each software package has an associated hardware configuration. Detailed reference designs are available.

RELATED LITERATURE

- 129907 VoicePath™ API-II Reference Guide VCP/VCP2-BT/AT/ATP/TH
- 129908 VoicePathTM API-II Reference Guide VCP/VCP2-NT
- 130145 VoicePath™ API-II Test Library User's Guide
- 139365 Le79128 NGVCP Data Sheet
- 081193 Le79238 Octal NGSLAC Data Sheet
- 136868 ZL79258 External Ringing NGSLAC Data Sheet
- 081555 Le79271 NGSLIC Data Sheet
- 126583 NGCC Hardware Design Guide

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MICROSEMI'S LINECARE™ SOFTWARE PACKAGE

Key Features

Microsemi's LineCare™ software package implements common features and functions to reduce complexity.

Key features of the LineCare[™] package include:

- Provides an abstract, uniform software interface for any combination of Microsemi voice products.
- Provides various design tools to help in the creation and organization of parameters specific to the design and market.
- Supports any combination of FXS lines configured for either loop-start signaling or ground-start signaling.
- Exposes device functionality for pulse-digit and flash decoding, ringing cadencing and tone cadencing.
- Proven on embedded operating systems such as Linux and VxWorks, and also compatible with non-OS environments; fits into common driver and static/dynamic library models.
- Can be used with single or multi-threaded applications.
- Supports various interrupt modes and both big-endian and little-endian host processors.
- Implemented in C code that is efficient, portable, and ANSI C compliant.
- Provides Self Test and Advanced line testing capabilities, including support for GR-844 and GR-909 equivalent line testing.
- Provides optional calibration for enhanced accuracy utilizing external calibration circuit in combination with NGVCP Advanced line measurement functions.
- Available in four different packages (Call Control, Basic Test, Advanced Test, and Advanced Test Plus) to fit the customer needs.
- Sample Quick Start Guide and Quick Start Application software provided with source code to facilitate startup and troubleshooting.
- NGVCP-Host (HBI/SPI) Hardware Verification Application source code and MPI Verification Application NGVCP loadable binary image provided to verify the interfaces between the NGVCP and the SLAC.
- Includes comprehensive documentation, an excellent starting point to help the developer quickly become familiar with the
 architecture.

The software package includes the following items.

VoicePath™ API-II

Microsemi's VoicePath™ Application Programmer Interface (VP API-II) is a C source code module that provides a standard software interface for implementing call control and line testing functions for a set of subscriber lines using Microsemi VTDs. The VP API-II abstracts and simplifies the details of controlling the Microsemi VTDs and allows software developers to focus on the application instead of the underlying hardware.

The API-II functions can be summarized into the following five groups:

- **Initialization functions:** These functions initialize various aspects of the NGVCP or perform the configuration required before a particular NGVCP feature may be used. Example of initialization features include:
 - Boot-load the firmware image into the NGVCP and start the DSP core inside the NGVCP.
 - Configure all lines with specified design parameters.
 - Calibrate all analog circuits of termination devices.
- Query Functions: The query functions provide several methods for servicing the NGVCP device's interrupts and checking
 the status of the lines. These functions allow the user to read option settings or line conditions, and to retrieve event
 contents or test results. Examples of query functions include:
 - On/Off hook, read loop conditions for a specific line.
 - Global device status for up to 128 lines.
 - Read various VoicePath™ API-II device options and test results.
 - **Control Functions:** These functions control the current line state and options that may change during run-time. Examples of control functions include:
 - Set a line to a desired state.
 - Place a cadenced DTMF call progress tone on the line.
 - Start metering on a particular line.
 - Set various VoicePath™ API-II device specific options.
- Test Functions: The test functions provide a toolbox of line tests and diagnostic utilities. Example of test functions include:
 - Perform Self Test on a particular line or the entire system.
 - Test primitives to support GR844 or GR909 line tests on any given channel.

 Helper Functions: The helper functions provide an interface for sending raw commands to a SLAC device controlled by the NGVCP over the MPI.

VoicePath™ Test Library

The VoicePath™ Test Library (VP-TL) is a collection of functions and data types that further utilize the line testing capabilities of Microsemi's VP API-II. These algorithms are executed on the host processor interfaced to Microsemi's NGVCP device combined with the NGCC devices through the VoicePath™ API-II.

The VP-TL offers the following key features:

- Performs a complete high-level test by running several VP API-II test primitives in sequence.
- Provides optimal default values for test input parameters that do not typically change at runtime, such as integration times, settling times, etc.
- Converts fixed-point results returned by the VP API-II test primitives into standard units that the application can readily use.
- Includes line Self-Testing to check for possible problems before putting a line into service.
- Includes line calibration for improving the testing accuracy by identifying correction factors that will be applied against
 measurement results.
- Allows line topology to be specified on a per line basis.
- Includes four versions of the Test Library, with increasing feature sets depending on the test package selected.

NGVCP Firmware

NGVCP firmware implements specific functions such as the line test primitives, advanced tone processing and cadencing. The software package controls the NGVCP device. The NGVCP device's registers and commands are abstracted by the VP API-II which is the communication layer between the NGVCP device and the customer's host processor. The NGVCP firmware is currently available in three variations NT, BT, and AT. The AT firmware is included in both the AT and ATP release packages. The software packages are:

- NT Includes all supported call control features.
- BT Includes all supported call control features plus the GR909 equivalent line testing.
- AT Includes all the features of the BT package plus the GR844 equivalent line testing.
- ATP Includes all the features of the AT package, additional line diagnostic tests, and a line calibration routine for increased accuracies.

Design Toolset

Microsemi products can be configured to meet standards worldwide, including custom requirements. To address such varying system-level specifications, Microsemi provides tools like WinSLACTM and Profile Wizard to help engineers generate design data. The design data provided by these tools is organized into profiles to meet specific system requirements. The data for each profile is created with the Profile Wizard application. Profiles can be generated for the following design parameters:

- System Profile The System Profile is a data array that contains set-and-forget parameters for the event mask, clocks, etc., and for other global configuration options.
- AC Profile The AC Profile is a transmission characteristic profile. The AC profile holds the SLAC device's gain block and
 filter block commands and data. Each AC Profile is designed to address the specific AC transmission requirements for a
 given design. In general, AC Profiles are used to address the varying requirements of different market segments.
- DC Profile The DC Profile holds the SLAC device's DC feed and Loop Supervision command and data. Each DC profile is designed to address the specific DC feed and Loop Supervision requirements of a given design. Examples of different DC feed profiles include a Constant Current Profile and a Resistive Feed Profile.
- Ringing Profile The Ringing Profile contains the necessary commands and data to set up the ringing generator of a
 SLAC device. Different Profiles can be used to vary the ringing characteristics of a line. Options available in the Ringing
 Profile include: ringing waveform, frequency, amplitude, DC offset, ring trip detector mode and a selection of internal or
 external ringing.
- Metering Profile The Metering Configuration Profile contains the necessary commands and data to set up the Pulse Meter Signal Generator of the SLAC device. The parameters configured include voltage limits.
- **Tone Profile** The Tone Profile defines the various call progress tones that might be used in a system. The tones include dial tone, busy, ring-back, and reorder. The Tone Profiles are used to address worldwide market variations.
- Tone Cadence Profile The Tone Cadence Profile defines the various cadences that might be used in a system for call progress tones. The Tone Cadence Profiles are used to address market variations.
- Ring Cadence Profile The Ring Cadence Profile defines the various cadences that might be used in a system for ringing.
 The Ring Cadence Profiles are used to address market variations.
- Caller ID Defines the various Caller Line Identity (CLI) types that might be used in a system. The Caller ID Profiles are

used to address the market variations that exist around the world.

The NGVCP contains internal tables for each of the profile types. This allows a fixed number (as defined in the Profile Table section of the *VoicePath™ API-II Reference Guide*) of each profile type to be stored in the NGVCP. When the host application requires the services of a particular profile for a function, it can simply refer to the profile by its index in the NGVCP device's profile table. Alternatively, the host application can maintain some (or all) of the needed profiles in the host, and pass them to the NGVCP for any function call that requires them.

Once the profiles have been created, they can be compiled into the user's application and passed into the VoicePathTM API-II. Then, the application can either load the profiles into the NGVCP, keep the profiles on the host and download them on demand, or perform a combination of the two methods.

Profile Wizard and WinSLAC are Microsoft[®] Windows[®] based applications that are part of the NGCC Design Kit and are used to create the various profiles needed to fulfill the specific market requirements.

SYSTEM ARCHITECTURE

<u>Figure 1</u> illustrates a typical system block diagram incorporating the software block diagram and a detailed block diagram of the underlying hardware combining the NGVCP and the NGCC line termination architecture. The LineCareTM software requires the System Services Layer and Hardware Abstraction Layer to operate correctly. The following sections describe each of the blocks.

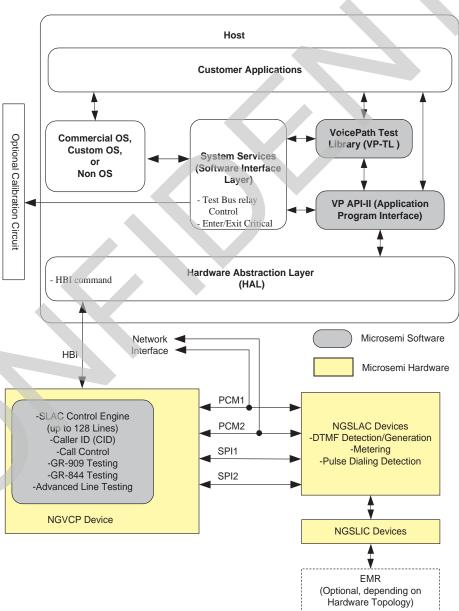


Figure 1. NGCC System Architecture with NGVCP

Software Architecture

Customer Application

This block represents the user's *line management* module that performs tasks such as initializing the system, configuring lines, changing line states in response to line events and other inputs, switching digitized voice traffic, line testing etc. These functions may be distributed across a complex system. Microsemi provides example applications as part of the NGVCP software package.

Operating System

This block represents whatever operating system (if any) the user is running on the host processor. The VP API-II does not directly utilize any operating system resources (e.g. queues, semaphores, etc.). The application developer may use operating system features such as tasks or shared memory with the VP API-II. Chapter 3 in the API Reference Guide covers using the VP API-II in a multitasking environment in detail.

System Services Layer

The System Services Layer abstracts platform-specific functions such as test relay control and other customer specific functions. This layer derives the functions required by the VP API-II from the facilities provided by the underlying hardware or operating system. This module is also platform-dependent and must be implemented by the VP API-II user. Microsemi provides example System Services Layer source code.

The System Service Layer should contain different procedures to control the various states of the calibration circuit when such circuit is present. These procedures will be called by the Test Library whenever a specific calibration load is required.

VoicePath™ Test Library

The VoicePath™ Test Library (VP-TL) algorithms are executed on the host processor using the VoicePath™ API-II.

VoicePath™ API-II

The VP API-II is the core component of the software package. This software module runs on the host processor that controls Microsemi VTDs. This code is supplied by Microsemi and should not be modified by the application developer.

Hardware Abstraction Layer

The Hardware Abstraction Layer (HAL) provides access to Microsemi devices through the Host Bus Interface (HBI). The HAL software is platform-dependent and must be implemented by the VP API-II user. Microsemi provides example HAL source code with the NGVCP Software Package.

Host Bus Interface

The Host Bus Interface (HBI) provides a means for the host to communicate with the NGVCP. The HBI includes the Application, Transport, and Physical Layers of the NGVCP device's host interface.

The physical layer defines the electrical characteristics of the interface (pins, timings, etc.) between the host and the NGVCP. The NGVCP supports two different physical layers: a General Purpose Parallel Interface (GPI) and a Serial Peripheral Interface (SPI).

This layered architecture allows the host programmer to control the NGVCP independently of the chosen physical layer (8-bit vs. 16-bit, byte-framing vs. command-framing).

Hardware Architecture

The hardware consists of the Le79128 NGVCP, the Le79238 NGSLAC and the Le79271 NGSLIC Voice Termination Devices.

The NGVCP is a digital signal processor platform that performs all of the management required for controlling multiple SLAC devices, as well as all the sequencing necessary for advanced line test functionality. To the host processor, the NGVCP looks like a single 128-line voice controller. The host communicates directly with the NGVCP device(s) through the HBI and does not communicate directly with any of the individual SLAC devices controlled by the NGVCP. The host can choose to poll the NGVCP or service it by waiting for an interrupt to indicate that servicing is needed. Multiple NGVCP devices can be connected to the same host.

The NGVCP communicates with the SLAC device(s) through two SPI ports. The NGVCP has 32 General Purpose I/O pins of which 16 are used as chip selects and 16 are used as interrupts.

The API line mapping to the SPI bus is fixed as shown in <u>Table 1</u>. There are 128 channels, these are numbered from 0 to 127. At system initialization, a software line object needs to be created for each individual line and contains all parameters associated with that line (VpMakeLineObject). A line context pointer to this line object is also created. After the system initialization is completed, all VP API-II functions use the line context pointer as a channel identifier such that the host application code needs not be concerned with the NGVCP channel ID.

Table 1. NGVCP GPIO Chip Select and Interrupt Assignments

			Chip Sel	lect		Interru	pt
VCP channel ID	SPI Port #		GPIO	GPIO Pin#		GPIO	GPIO Pin#
0 to 7		CS0	16	36	INT0	0	76
8 to 15		CS1	17	7	INT1	1	77
16 to 23		CS2	18	8	INT2	2	78
24 to 31	1	CS3	19	12	INT3	3	79
32 to 39	- 	CS4	20	13	INT4	4	82
40 to 47		CS5	21	15	INT5	5	83
48 to 55		CS6	22	19	INT6	6	85
56 to 63		CS7	23	20	INT7	7	92
64 to 71		CS8	24	2	INT8	8	98
72 to 79		CS9	25	1	INT9	9	99
80 to 87		CS10	26	128	INT10	10	100
88 to 95	2	CS11	27	127	INT11	11	101
96 to 103		CS12	28	126	INT12	12	102
104 to 111		CS13	29	125	INT13	13	103
112 to 119		CS14	30	124	INT14	14	106
120 to 127		CS15	31	123	INT15	15	107

Hardware Topologies

Microsemi specifies standard topologies that define the hardware test architecture. This architecture defines the termination type for the VoicePath™ Test Library software. The software for NGCC currently supports five general hardware topologies. <u>Table 2</u> lists the hardware topologies and the supported termination types.

Table 2. VoicePath™ Test Library Supported Termination Types

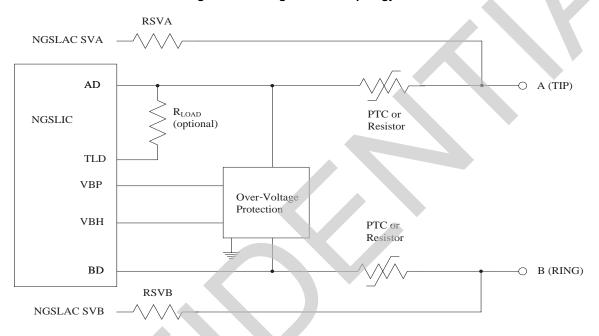
Hardware Topologies	Software Termination Types	Device	Description
Configuration C	VP_TERM_FXS_GENERIC	NGVCP	Generic FXS termination
Configuration D	VP_TERM_FXS_TI	NGVCP	FXS termination with Test-In relay
Configuration E	VP_TERM_FXS_RR	NGVCP	FXS termination with Ringing relay
Configuration E	VP_TERM_FXS_RR_MW	NGVCP	FXS termination with Ringing and Message Waiting relays
Configuration F	VP_TERM_FXS_RR_TI	NGVCP	FXS termination with Ringing and Test-In relays

Configuration C Topology (VP_TERM_FXS_GENERIC)

Features:

- POTS service.
- Foreign voltages in excess of the SLIC power rail voltages can be measured when the PTCs are activated or if the fault current doesn't exceed the SLIC current drive capability.
- The test load resistor is used for self-testing.
- No disconnect relay. There is no means to disconnect the line from the loop during inward looking test, therefore Self Test
 can only be performed in the factory. The published Self Test accuracies are given for production testing only, when no loop
 is connected to the equipment port. If Self Tests are performed in the field, the host application needs to take into account
 any loop impedance present.

Figure 2. Configuration C Topology



This configuration supports the relay states listed in <u>Table 3</u>. See the *VoicePath™ API-II Reference Guide* for details of the VpSetRelayState() function. Connectivity for the various relay states is depicted in <u>Table 4</u>.

Table 3. Software States for Configuration C

Software State (VpRelayState)	Description
VP_RELAY_NORMAL	Test load switch off
VP_RELAY_TALK	Test load switch off
VP_RELAY_BRIDGED_TEST	Test load switch on

Table 4. Configuration C Bus Connections

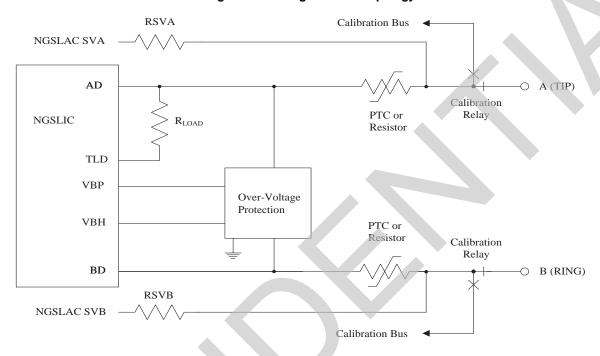
Software State	AD/BD	SVA/SVB	Rload	TIP/RING
VP_RELAY_NORMAL	•	•		•
VP_RELAY_TALK	•	•		•
VP_RELAY_BRIDGED_TEST	•	•	•	•

Configuration D Topology (VP_TERM_FXS_TI)

Features:

- POTS service with a relay to connect to a calibration circuit for In-Service Calibration and Self-Testing.
- Foreign voltages in excess of the SLIC power rail voltages can be measured when the PTCs are activated or if the fault current doesn't exceed the SLIC current drive capability.
- The Calibration relay is used to disconnect the loop during self-testing.
- Self-test is performed using the calibration circuit or a per-channel test load resistor.
- Calibration can be performed using a shared circuit connected to the Calibration Bus.

Figure 3. Configuration D Topology



This configuration supports the relay states listed in <u>Table 5</u>. See the *VoicePath™ API-II Reference Guide* for details of the VpSetRelayState() function. Connectivity for the various relay states is depicted in <u>Table 6</u>.

Table 5. Software States for Configuration D

Software State (VpRelayState)	Description
VP_RELAY_NORMAL	Test load switch off
VP_RELAY_TALK	Test load switch off
VP_RELAY_TEST	Test load switch off, Calibration relay activated
VP_RELAY_DISCONNECT	Test load switch off, Calibration relay activated
VP_RELAY_BRIDGED_TEST	Test load switch on
VP_RELAY_SPLIT_TEST	Test load switch on, Calibration relay activated

Table 6. Configuration D Bus Connections

Software State	AD/BD	SVA/SVB	Rload	Calibration Bus	TIP/RING
VP_RELAY_NORMAL	•	•			•
VP_RELAY_TALK	•	•			•
VP_RELAY_TEST	•	•		•	
VP_RELAY_DISCONNECT	•	•		•	
VP_RELAY_BRIDGED_TEST	•	•	•		•
VP_RELAY_SPLIT_TEST	•	•	•	•	

Configuration E Topology (VP TERM FXS RR)

Features:

- POTS service with external ringing.
- Foreign voltages in excess of the SLIC power rail voltages can be measured when the PTCs are activated, if the fault current doesn't exceed the SLIC current drive capability, or by operating the ringing relay to disconnect the SLIC drivers from the external port. The last option is only available if the ringing bus can be made high impedance during the foreign voltage test.
- The test load resistor is used for self-testing.
- This configuration does not use a VBP supply, therefore some test restrictions apply.
- No disconnect relay. There is no means to disconnect the line from the loop during inward looking test, therefore Self Test can only be performed in the factory. The published Self Test accuracies are given for production testing only, when no loop is connected to the equipment port. If Self Tests are performed in the field, the host application needs to take into account any loop impedance present.

Figure 4. Configuration E Topology Internal Ringing Bus NGSLAC SVA Ringing Return < R_{FEED} Ringing Bus Relay AD A (TIP) Ringing/ Fuse C_{TIP} Reset Relay R_{LOAD} (optional) **NGSLIC** (optional) TLD Over-Voltage **VBH** Protection Ringing/ Reset Relay BD B (RING) Fuse \boldsymbol{R}_{FEED} NGSLAC XSB (optional) NGSLAC SVB NGSLAC IO 0 Ringing/Reset Relay Ringing Bus Relay Board I/O pin NGSLAC XSC Ringing Internal Ringing Bus Generator Ringing Bus Relay (optional)

This configuration supports the relay states listed in <u>Table 7</u>. See the *VoicePath* TM *API-II Reference Guide* for details of the VpSetRelayState() function.

Connectivity for the various relay states is depicted in Table 8.

Table 7. Software States for Configuration E

Software State (VpRelayState)	Description
VP_RELAY_NORMAL	Ringing relay on or off based on line state, test load released
VP_RELAY_TALK	Ringing/Reset relay released, test load released
VP_RELAY_RINGING	Ringing relay active, test load released
VP_RELAY_BRIDGED_TEST	Ringing/Reset relay released, test load active
VP_RELAY_RESET ¹	Reset relay active, test load released, ringing bus relay active

^{1.} Note: The application developer must implement the VptlSysCaptureRingingBus() and the VptlSysReleaseRingingBus() functions in order to use the VP_RELAY_RESET state. The ringing bus relay is controlled by those two functions, not by the VpSetRelayState() function. Refer to the VoicePathTM API-II Test Library User's Guide for more details.

Table 8. Configuration E Bus Connections

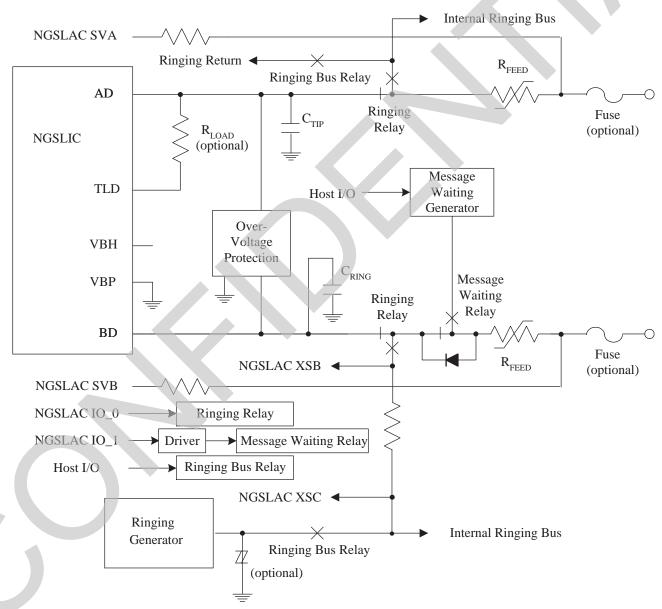
Software State	AD/BD	SVA/SVB	Rload	Ringing	TIP/RING
VP_RELAY_NORMAL ¹	•	•			•
VP_RELAY_NORMAL ²		•		•	•
VP_RELAY_TALK	•	•			•
VP_RELAY_RINGING		•		•	•
VP_RELAY_BRIDGED_TEST	•	•	•		•
VP_RELAY_RESET		•			•
1. Non-ringing line state. 2. Ringing li	ne state.			1	'

Configuration E Topology (VP_TERM_FXS_RR_MW)

Features:

- POTS service with external ringing and Message Waiting signalling.
- Foreign voltages in excess of the SLIC power rail voltages can be measured when the PTCs are activated, if the fault
 current doesn't exceed the SLIC current drive capability, or by operating the ringing relay to disconnect the SLIC drivers
 from the external port. The last option is only available if the ringing bus can be made high impedance during the foreign
 voltage test.
- The test load resistor is used for self-testing.
- This configuration does not use a VBP supply, therefore some test restrictions apply.
- No disconnect relay. There is no means to disconnect the line from the loop during inward looking test, therefore Self Test
 can only be performed in the factory. The published Self Test accuracies are given for production testing only, when no loop
 is connected to the equipment port. If Self Tests are performed in the field, the host application needs to take into account
 any loop impedance present.

Figure 5. Configuration E Topology



This configuration supports the relay states listed in <u>Table 9</u>. See the *VoicePath* TM *API-II Reference Guide* for details of the VpSetRelayState() function.

Connectivity for the various relay states is depicted in <u>Table 10</u>.

Table 9. Software States for Configuration E

Software State (VpRelayState)	Description
VP_RELAY_NORMAL	Ringing relay on or off based on line state, test load released, message waiting relay off
VP_RELAY_TALK	Ringing relay off, test load released, message waiting relay off
VP_RELAY_RINGING	Ringing relay active, test load released, message waiting relay off
VP_RELAY_BRIDGED_TEST	Ringing relay off, test load active, message waiting relay off
VP_RELAY_LAMP_ON	Ringing relay off, test load released, message waiting relay on
VP_RELAY_RESET ¹	Ringing relay active, test load released, message waiting relay off, ringing bus relay active

^{1.} Note: The application developer must implement the VptlSysCaptureRingingBus() and the VptlSysReleaseRingingBus() functions in order to use the VP_RELAY_RESET state. The ringing bus relay is controlled by those two functions, not by the VpSetRelayState() function. Refer to the VoicePathTM API-II Test Library User's Guide for more details.

Table 10. Configuration E Bus Connections

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Software State	AD/BD	SVA/SVB	Rload	Ringing	TIP/RING	Message Waiting
VP_RELAY_NORMAL ¹	•	•			•	
VP_RELAY_NORMAL ²		•	-	•	•	
VP_RELAY_TALK	•	•			•	
VP_RELAY_RINGING		•		•	•	
VP_RELAY_BRIDGED_TEST	•	•	-		•	
VP_RELAY_LAMP_ON ³		•			•	•
VP_RELAY_RESET					•	

^{1.} Non-ringing line state. 2. Ringing line state.

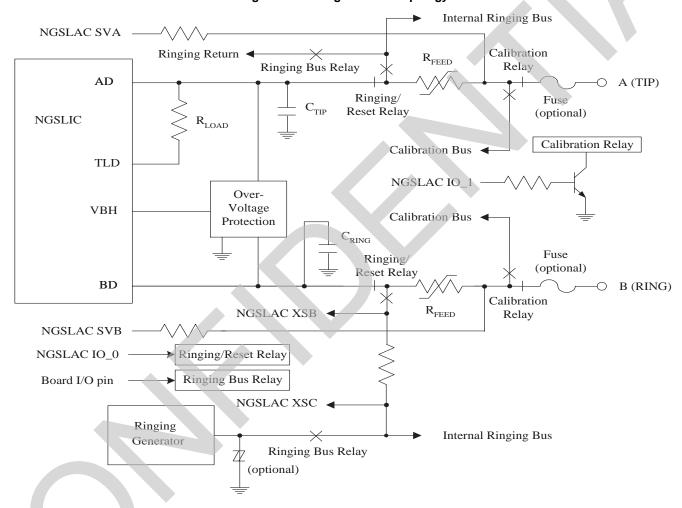
^{3.} Line feed reverts to AD/BD via a diode in case of an off-hook, because the message waiting generator goes into current limit.

Configuration F Topology (VP_TERM_FXS_RR_TI)

Features:

- POTS service with external ringing and a relay to connect to a calibration circuit for In-Service Calibration and Self-Testing.
- Foreign voltages in excess of the SLIC power rail voltages can be measured when the PTCs are activated, if the fault
 current doesn't exceed the SLIC current drive capability, or by operating the ringing relay to disconnect the SLIC drivers
 from the external port. The last option is only available if the ringing bus can be made high impedance during the foreign
 voltage test.
- The Calibration relay is used to disconnect the loop during self-testing.
- Self-test is performed using the calibration circuit or a per-channel test load resistor.
- This configuration does not use a VBP supply, therefore some test restrictions apply.
- Calibration can be performed using a shared circuit connected to the Calibration Bus.

Figure 6. Configuration F Topology



This configuration supports the relay states listed in <u>Table 11</u>. See the *VoicePath*TM *API-II Reference Guide* for details of the VpSetRelayState() function.

Connectivity for the various relay states is depicted in Table 12.

Table 11. Software States for Configuration F

Software State (VpRelayState)	Description
VP_RELAY_NORMAL	Ringing relay on or off based on line state, test load released
VP_RELAY_TALK	Ringing/Reset relay released, test load released
VP_RELAY_RINGING	Ringing relay active, test load released
VP_RELAY_BRIDGED_TEST	Ringing/Reset relay released, test load active
VP_RELAY_RESET ¹	Reset relay active, test load released, ringing bus relay active
VP_RELAY_TEST	Ringing/Reset relay released, test load released, Calibration relay activated
VP_RELAY_DISCONNECT	Ringing/Reset relay released, test load released, Calibration relay activated
VP_RELAY_SPLIT_TEST	Ringing/Reset relay released, test load active, Calibration relay activated
VP_RELAY_RINGING_TEST	Ringing/Reset relay active, test load released, Calibration relay activated

^{1.} Note: The application developer must implement the VptlSysCaptureRingingBus() and the VptlSysReleaseRingingBus() functions in order to use the VP_RELAY_RESET state. The ringing bus relay is controlled by those two functions, not by the VpSetRelayState() function. Refer to the VoicePathTM API-II Test Library User's Guide for more details.

Table 12. Configuration F Bus Connections

Software State	AD/BD	SVA/SVB	Rload	Ringing	Calibration Bus	TIP/RING
VP_RELAY_NORMAL ¹	•					•
VP_RELAY_NORMAL ²		•		•		•
VP_RELAY_TALK	•	•				•
VP_RELAY_RINGING		•		•		•
VP_RELAY_BRIDGED_TEST	•	•	•			•
VP_RELAY_RESET		•				•
VP_RELAY_TEST	•	•			•	
VP_RELAY_DISCONNECT	•	•			•	
VP_RELAY_SPLIT_TEST	•	•	•		•	
VP_RELAY_RINGING_TEST		•		•	•	
1. Non-ringing line state. 2. Ringing line	ne state.	•	+	•	*	

Calibration

The VoicePath™ Test Library delivered with the NGVCP ATP package includes a calibration function that can be used to improve the testing accuracy. Performing the line testing on an external calibration circuit (see <u>Figure 7</u>) identifies the correction factors that will be applied against subsequent results. Calibration is performed on a per-line basis. Calibration factors for each line are to be stored individually, and applied individually.

Two classes of calibration can be performed, Factory Calibration and In-Service Calibration.

Factory Calibration would be performed at the time the line card is manufactured, prior to the line card being shipped. Correction factors would be stored on the respective line card board. Using Factory Calibration requires the user to store the calibration factors in non-volatile memory and re-apply these factors as needed.

In-Service Calibration can be performed after the line card is deployed. To achieve this, a test relay is required.

Configuration C and E do not include a test-in relay and can only be calibrated at the factory by applying the calibration circuit directly to the line's A and B leads.

Configuration D and F have a relay that can provide Calibration Bus access to perform In-Service Calibration. Of course the Factory Calibration can also be performed with Configuration D and F.

LINE TESTING

Time Slot Requirements

Line test works in linear mode so a minimum of two adjacent time slots per channel are required. The 15-kHz noise test requires 8 adjacent time slots. For line test the NGVCP keeps an image of the time slot assignments, so there is no need to do a reassignment after the test completes. The NGVCP does not however keep track of adjacent time slot usage, so the host must ensure that the adjacent time slot is not assigned. As an example, if there is a voice channel assigned to time slot 5, when you request a test to that same channel, the NGVCP will know the channel is on time slot 5, but the NGVCP will not check to see if time slot 6 is available - the NGVCP assumes this time slot is available.

Another way to manage time slot control is to put the voice time slots adjacent to each other and reserve a block of 20 time slots for testing. The block of 20 time slots will accommodate the following valid combinations:

- · Four regular transmission tests: 8 time slots.
- One 15-kHz test plus three regular transmission tests: 14 time slots.
- Two 15-kHz test plus two regular transmission tests: 20 time slots.

Common time slot management options:

- Put all channels contiguous, one after each other, and allocate 20 time slots for line testing. Always reallocate the channel time slot before executing any test requiring PCM access. Or,
- Skip every second channel, leaving an empty time slot between each time slot in use, and allocate 16 time slots to line
 testing. Only reallocate the channel time slot before executing a 15-kHz noise test. Regular transmission tests do not
 require a time slot re-allocation.

Of course the host must keep a record of the testing time slots already in use and grab an empty one when starting a new test.

All transmission tests use the PCM bus to transfer signal samples from the SLAC to the NGVCP. Some impedance or voltage measurements also use the PCM bus for the same purpose. Moreover, this may change over time if new tests are developed, or if existing tests are improved. Therefore, it is recommended to always assume the PCM bus will be used and to ensure the channel under test uses a non-conflicting time slot before executing any test.

The Le79128 NGVCP is intended to be used with two PCM highways.

Device Level Test Restrictions

Line test restrictions at the device level are:

- Up to 4 lines in line testing simultaneously running per NGVCP.
 - Of the 4 lines running line testing simultaneously, there is a limit of two simultaneous 15-kHz noise tests per NGVCP.
- Up to 2 lines in line testing simultaneously running per SLAC.
 - Of the 2 lines running line testing simultaneously, only one of these tests may be the 15-kHz noise test.

Line Test Packages

<u>Table 13</u> provides a complete list of the supported line test algorithms and their library names. The table also shows which configuration topology the algorithms can be used with and in which software package they're available.

Many of these tests will be used for GR-844 testing. A subset of these will be used for GR-909 testing. These tests are detailed in Table 14.

Table 13. NGVCP-NGCC Supported Line Test Packages

				C	onfig.	NGVCP Packages				
Algorithm Names	Description	VP-Test Library Names	С	D	E	F	NT	BT AT		ATF
Calibration	To measure correction factors that can be used to improve measurement and DC feed accuracy. Factory Calibration.	- VPTL_TID_CALIBRATE								•
Calibration	To measure correction factors that can be used to improve measurement and DC feed accuracy. Factory or In-Service Calibration.	VETE_TID_CALIBRATE		•		•				•
Apply Calibration	To transfer the calibration factors into the SLAC in order to improve the testing and DC feed accuracy.	VPTL_TID_APPLY_CALIBRATION	•	•	•	•				•
Foreign DC Voltage Test	To measure the DC foreign voltage present in the loop while the line card is in a high impedance state. A low-pass filter is used to filter out any AC voltage present on the line.	VPTL_TID_OPEN_DC_VOLTAGE	•	•	•2	•2		•	•	•
Foreign AC Voltage Test	To measure the AC foreign voltage present in the loop. A high pass filter is used to filter out any DC voltage present on the line.	VPTL_TID_OPEN_AC_VOLTAGE	•	•	•3	•3		•	•	•
DC Loop Resistance Test	To measure low loop impedance values generally less than 4K Ohms using either Forward/Reverse Battery or Offset Compensation algorithms.	VPTL_TID_DC_LOOP_RES	•	•	•	•		•	•	•
Generic Insulation Resistance	Similar to Three-Element Insulation Resistance Test except user can control voltage and measurement times.	VPTL_TID_GEN_RES	•	•	● 6	•6		•	•	•
Three-Element Insulation Resistance Test	To measure the resistances connected between Tip and ground, Ring and ground, and Tip to Ring. The test can also measure the foreign DC voltage and current. The test can measure foreign voltage sources in excess of the SLIC power supply rails.	VPTL_TID_3ELE_RES	•	•	•4	•4		•	•	•
Four-Element Insulation Resistance Test	To measure the resistances connected between Tip and ground, Ring and ground, Tip to Ring, and Ring to Tip using dual polarities for the metallic test signal.	VPTL_TID_4ELE_RES	•	•	•4	•4			•	•
Five-Element Insulation Resistance Test	To measure the resistances connected between Tip and ground, Ring and ground, and Tip to Ring as well as resistances between Tip and Battery and Ring and battery.	VPTL_TID_5ELE_RES	•	•	•4	•4				•
Six-Element Insulation Resistance Test	Similar to Five-Element Resistance with the addition of Tip to Ring and Ring to Tip resistance differentiation in order to detect a non-linear element such as a diode.	VPTL_TID_6ELE_RES	•	•	•4	•4				•

				Со	nfig.	N	jes		
Algorithm Names	Description	VP-Test Library Names	С	D	E	F NT	BT	AT	ATP
Master Socket Test	To detect the presence of an M-Socket used in Hong Kong and a passive test termination (PPA - Passiver Prüfabschluss) used in the German telephony network. An M-Socket termination diagram is presented in Figure 8. A PPA termination diagram is presented in Figure 9.	VPTL_TID_MSOCKET	•						•
CO Splitter Signature Detection	To measure the signature network of a POTS splitter filter located at the CO end of the loop. Two zener options are provided, VPTL_ZENER_24V and VPTL_ZENER_36V. CO splitter signature types are presented in Figure 12.	VPTL_TID_CO_SPLITTER	·	•	•5	•5			•
CPE Splitter and IAD Signature Detection	To detect CPE splitter and Integrated Access Device signature types. Zener and mode input parameters allow for discrimination of the various networks. Signature network diagrams are presented in Figure 10 and Figure 11.	VPTL_TID_CPE_SPLITTER_IAD	•	•	•	•			•
ISDN Terminal Detection Test	To detect if an ISDN terminal is connected at the customer end of the loop. Targeted at detecting a German NTBA (Network Termination Basisanschluss).	VPTL_TID_ISDN_TERMINAL	•	•	•	•			•
Three-Element Capacitance Test	To measure the capacitances connected between Tip and ground, Ring and ground, and Tip to Ring. This test also measures foreign AC voltage. The test can measure foreign voltage sources in excess of the SLIC power supply rails.	VPTL_TID_3ELE_CAP	•	•	•	•		•	•
Generic Three-Element Capacitance Test	Similar to Three-Element Capacitance Test except user can control voltage, frequency and measurement times. This test can be used to implement a low capacitance phone detection algorithm.	VPTL_TID_GEN_3ELE_CAP	•	•	•	•		•	•
Receiver Off-Hook Test	To distinguish between a receiver taken off hook and a line short.	VPTL_TID_ROH	•	•	•	•	•	•	•
Distance to Open Test	To diagnose a line to locate a cable cut. Returns the distance in meters between the central office and the cable cut.	VPTL_TID_DISTANCE_TO_OPEN	•	•	•	•		•	•
Foreign AC Currents Test	To measure the AC current flowing in each lead when the line is set to a specific common mode voltage.	VPTL_TID_FOREIGN_AC_CURRENT	•	•	•	•		•	•
Ringer Equivalency Number Test	To measure REN characteristics of regular or electronic phones.	VPTL_TID_REN	•	•	● 6	•6	•	•	•
Ringer Equivalency Number with Phase	To measure the REN magnitude and phase of a phone attached to the line taking into account the loop characteristics.	VPTL_TID_REN_PHASE	•	•	● 6	•6	•	•	•

				Co	nfig.	7	NGVCP Package			jes
Algorithm Names	Description	VP-Test Library Names	С	D	E	F	NT	BT	AT	ATP
DTMF and Pulse Digit Measurement Test	VPII III) DIME PUI SE MSRMNI								•	•
Noise Measurement Test	To measure the sum of the line circuit noise and the subscriber loop noise using one of the many weighting filters – Flat, 3-kHz, 15-kHz, 3.4-kHz, CMSG, D-Filter, Psophometric.	VPTL_TID_NOISE		·		•		•	•	•
Signal to Noise Ratio Test	To measure the signal to noise ratio due to circuit noise and quantization distortion while applying a 1010 Hz test tone to the loop.	VPTL_TID_SNR_QNTZ_DIST	•	•		•				•
Arbitrary Single Tone Measurement Test	To measure the frequency and level of an arbitrary single tone that may be present on the loop.	VPTL_TID_ARB_TONE	•	•	•	•				•
Tone Generation Test	To generate specific tones to a specific line. (Generate up to 4 tones)	VPTL_TID_TONE_GEN	•	•	•	•			•	•
Unbalanced Tone Generation	To generate a tracing tone on a single wire.	VPTL_TID_UNBAL_TONE	•	•	● 6	•6		•	•	•
Trans-Hybrid Loss Test	To measure the Trans Hybrid Loss of the line circuit under test.	VPTL_TID_TRANS_HYBRID_LOSS	•	•	•	•		•	•	•
Draw and Break Dial Tone Test	Apply an off-hook load and detect the presence of dial tone on the loop. Return the characteristics of the tones (amplitudes and frequencies). Then, dial a simulated digit to verify proper removal of the dial tone signal.	VPTL_TID_DRAW_BREAK_DIALTONE	•1	•	•1	•			•	•
Inward Current Test	When used as a test head, to verify the AC/DC current generated by another line.	VPTL_TID_INWRD_CUR		•		•				•
DC Feed Self-Test	To verify the capability of the SLIC to drive currents into a load and to measure the voltage developed across it.	VPTL_TID_DC_FEED_SELF_TEST	•1	•	•1	•		•	•	•
On/Off Hook Self-Test	To verify the capability of the line card circuitry to detect on-hook and off-hook conditions.	VPTL_TID_ON_OFF_HOOK_SELF_TEST	•1	•	•1	•		•	•	•
Ringing Self-Test	To verify the capability of the line card circuitry to generate a ringing voltage at the desired amplitude and to perform ring trip upon application of an off-hook.	VPTL_TID_RINGING_SELF_TEST	•1	•		•		•	•	•
Ringing Monitor Test	To measure the ringing voltage while applying normal ringing on a terminating call.	VPTL_TID_RINGING_MONITOR_TEST	•	•	•	•		•	•	•
Metering Self-Test	To verify the capability of the line card circuitry to generate a metering pulse.	VPTL_TID_METERING_SELF_TEST	•1	•	•1	•			•	•
Transmission Self-Test	To verify the capability of the line card circuitry to pass Voice Frequency signals in the D/A and in the A/D directions.	VPTL_TID_TRANSMISSION_SELF_TEST	•1	•	•1	•		•	•	•

				Co	onfig.	N	jes		
Algorithm Names	Description	VP-Test Library Names	С	D	E	F NT	BT	AT	ATP
Dialing Self-Test	To verify the capability of the line card circuitry to detect pulse dialing and DTMF dialing.	VPTL_TID_DIALING_SELF_TEST	•1	•	•1			•	•
Line Circuit Currents and Voltages	Measure AC or DC current or voltage while providing service.	VPTL_TID_MONITOR_IV		•		•	•	•	•
AC Transmission Test	To verify the channel transmission characteristics.	VPTL_TID_AC_TRANS	•1	•	• 1	•			•
Repetitive AC Transmission Test	To verify the channel transmission characteristics.	VPTL_TID_AC_TRANS_REP	•1	•	.1	•			•
Howler Test	British, Australian and North American Howler Tone generation.	VPTL_TID_HOWLER_TEST		•	•	•		•	•
Fuse Test	To verify the integrity of the fuses on the Tip and Ring leads.	VPTL_TID_FUSE_TEST	•	•	•	•			•
Read Loop and Battery Conditions	Read the loop conditions and, high, low and positive battery voltages.	VPTL_TID_LOOP_BAT_COND_TEST	•	•	•7	•7	•	•	•
GR909-All Test	To execute the complete list of GR-909 tests in less than 2 seconds.	VPTL_TID_GR909_ALL	•	•	•	•	•	•	•
Combined Multi-Test	To execute a series of voltage, resistance, and capacitance tests.	VPTL_TID_MULTI_TEST	•	•	•2,3, 4	•2,3, 4		•	•
Susceptance Test	Measures the complex admittance of the Tip to ground, Ring to ground, and Tip to Ring branches using a sinewave with phase control and reports the conductance and susceptance of each branch.	VPTL_TID_SUSCEPTANCE_TEST	•	•	•4	•4			•
Foreign AC Voltage with Frequency Measurement Test	To measure the AC foreign voltage present in the loop and the frequency of those foreign signals. A high pass filter is used to filter out any DC voltage present on the line.	VPTL_TID_OPEN_AC_VOLTAGE_FREQ	•	•	•3	•3			•
Extended Master Socket Test	To detect the presence of an M-Socket used in Hong Kong and a passive test termination (PPA - Passiver Prüfabschluss) used in the German telephony network. An M-Socket termination diagram is presented in Figure 8. A PPA termination diagram is presented in Figure 9. This test uses results from the Four-Element Insulation Resistance Test to improve execution time.	VPTL_TID_EXT_MSOCKET	•	•	•	•			•
Electronic Ringer Detection	Generates a voltage ramp with an amplitude higher than the zener voltage of an electronic ringer network, then measures the various elements of this non-linear metallic impedance.	VPTL_TID_ELE_RINGER_DET	•	•	•8	•8			•
Extended Group Test	To execute Foreign DC Voltage, Foreign AC Voltage, Four-Element Insulation Resistance, Three-Element Capacitance, and Susceptance Tests within a single call. Also performs receiver off-hook, ringer detection, and PPA.	VPTL_TID_EXT_GROUP_TEST	•	•	•2,3, 4,8	•2,3, 4,8			•

			Config.			NGVCP Packages				
Algorithm Names	Description	VP-Test Library Names	С	D	E	F	NT	BT	AT	ATP
Fast Group Test	To execute Foreign DC Voltage, Foreign AC Voltage, Four-Element Insulation Resistance, Three-Element Capacitance, and Susceptance Tests within a single call. Also performs receiver off-hook, ringer detection, and PPA.	VPTL_TID_FAST_GROUP_TEST	•	•	•2,3, 4,8	•2,3, 4,8				•
Continuous Tone Generation Test	To generate a continuous tracing tone at desired frequency and amplitude across a 600 ohm load.	VPTL_TID_TONE	•	•	•	•				•

- 1. Configuration C and E have no disconnect relay. If there is no other means to disconnect the line from the loop during inward looking test, Self Tests can only be performed in the factory. The published Self Test accuracies are given for production testing only when no loop is connected to the equipment port. If the Self Tests are performed in the field, the host application needs to interpret the data accordingly, taking into account any loop impedance present.
- 2. Minor functional difference on how test is performed and reduced range with Configuration E and F for Foreign DC Voltage Tests. Refer to VoicePathTM API-II Test Library User's Guide for details.
- 3. Reduced range with Configuration E and F for Foreign AC Voltage Tests. Refer to VoicePathTM API-II Test Library User's Guide for details.
- 4. Range reduction in low resistance measurements with Configuration E and F for Resistance Tests. Refer to VoicePathTM API-II Test Library User's Guide for details.
- 5. With Configuration E and F, the VPTL_ZENER_36V option of this test is only supported if the VBH potential is adequate to support a 45 V metallic drive. Refer to VoicePathTM API-II Test Library User's Guide for details.
- 6. Some restrictions on the input parameter selection range apply with Configuration E and F due to the absence of a VBP supply. Refer to VoicePathTM API-II Test Library User's Guide for details.
- 7. Can not measure IMT and ILG currents when in the ringing mode.
- 8. Range reduction with Configuration E and F for Electronic Ringer Detection. Refer to VoicePathTM API-II Test Library User's Guide for details.

Table 14. GR-909 Tests and their corresponding Test Library Names

GR-909 test names	Description	Test Library Names
Outward loop testing		
Hazardous potential test AC Foreign voltage test AC	To measure the foreign AC Voltage present in the loop. A high pass filter is used to filter out any DC voltage present on the line.	VPTL_TID_OPEN_AC_VOLTAGE
Hazardous potential test DC	To measure the foreign DC Voltage	
Foreign voltage test DC	present in the loop while the card is in a high impedance state	VPTL_TID_OPEN_DC_VOLTAGE
Resistive fault test	To measure any resistive fault present between Tip and ground, Ring and ground, Tip and Ring.	VPTL_TID_3ELE_RES
Receiver off-hook test	To verify the difference between a receiver taken off-hook and a line short.	VPTL_TID_ROH
Ringer test	To measure the ringer equivalence number of a phone	VPTL_TID_REN
GR-909 tests	Performs all outward loop tests	VPTL_TID_GR909_ALL
Inward equipment testing		
DC feed test ¹	See DC Feed and On-OFF Hook Self Test definitions in <u>Table 13</u>	VPTL_TID_DC_FEED_SELF_TEST and VPTL_TID_ON_OFF_HOOK_SELF_TEST
Ringing test ¹	To verify the capability of the line card circuitry to generate a ringing voltage at the desired amplitude and to perform ring trip upon an off-hook event	VPTL_TID_RINGING_SELF_TEST
Two-wire channel loss ^{1, 2}	To measure the Trans Hybrid Loss of	VPTL_TID_TRANSMISSION_SELF_TEST or
Echo return loss ¹	the line circuit under test	VPTL_TID_TRANS_HYBRID_LOSS
Idle channel noise	To measure the sum of the line circuit noise and the subscriber loop noise using a C-Message filter	VPTL_TID_NOISE

Notes:

- 1. Requires the test load resistor as the termination.
- 2. Using open-circuit as the reflect termination.

Measurement Range and Accuracy

Table 15 presents measurement ranges and accuracies for the Configuration C topology. Table 16 presents measurement ranges and accuracies for the Configuration D topology. Table 17 presents measurement ranges and accuracies for the Configuration E topology. Table 18 presents measurement ranges and accuracies for the Configuration E topology. Accuracies are listed for each calibration option and are specified for the recommended sense resistor tolerance. Accuracies apply to the recommended application circuits and parts lists that are defined in the NGCC Hardware Design Guide, Document ID 126583. Refer to the notes following the tables for additional information.

CONFIGURATION C

Table 15. Configuration C Measurement Range and Accuracy¹¹

CONFIGURATION C

			No Calibration					Eactor	tion	
				RSVA/RSVB 0.5%, 100 ppm				RSVA/RS\	ry Calibra	
	T	T		KSVA/KS	/B 0.5%, 1			K5VA/K5V	/B 0.5%, 1	• •
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
			-1000	-400		±2.2% & ±3.0 V	-1000	-400		±1.95% & ±1.5 V
VPTL_TID_OPEN_DC_VOLTAGE	Tip or ring voltage	Notes 1, 3, 8, 10, 13	-400	400	V	±1.9% & ±1.0 V	-400	400	V	±1.75% & ±0.5 V
VFTL_TID_OFEN_DC_VOLIAGE	Tip of fing voltage		400	1000		±2.2% & ±3.0 V	400	1000		±1.95% & ±1.5 V
		AC induction rejection	0	280	Vrms	> 40 dB	0	280	Vrms	> 40 dB
			0	280		±1.9% &	0	280		±1.75% &
		Notes 1, 3, 8, 10, 14	Ŭ		Vrms	±0.05 V	ŏ		Vrms	±0.05 V
	Tip or ring voltage		280	700		±2.2% & ±0.2 V	280	700		±1.95% & ±0.2 V
		Frequency Range	50	200	Hz		50	200	Hz	
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB
VPTL_TID_OPEN_AC_VOLTAGE			0	280		±2.65% &	0	280	Vrms	±1.8% &
		Notes 1, 3, 8, 10, 14			Vrms	±0.05 V				±0.05 V
	Differential voltage		280	700		±3.1% & ±0.2 V	280	700		±2.5% & ±0.2 V
		Frequency Range	50	200	Hz		50	200	Hz	
		Common-mode Rejection	0	280	Vrms	< 2%	0	280	Vrms	< 2%
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB
	ILG current		0	80	mA	±3.2% &	0	80	mA	±3.2% &
VPTL_TID_MONITOR_IV	120 00.10111	Notes 3, 8, 13, 14, 15				±1.0 mA				±1.0 mA
	IMT current	, , , , , , , ,	0	80	mA	±4.0% &	0	80	mA	±2.5% &
		· ·	_			±1.0 mA				±0.75 mA
	Test with offset	Notes 2, 3, 8	0	4	kΩ	±6% & ±10 Ω	0	4	kΩ	±4.5% & ±10 Ω
VPTL_TID_DC_LOOP_RES	compensation	Note 4	5	70	mA	±4.0% & ±2.0 mA	5	70	mA	±2.5% & ±0.75 mA
			1	10	kΩ	±5% & ±20 Ω	1	10	kΩ	±4.5% & ±20 Ω
	Mechanical ringer test	Notes 3, 8	10	100	kΩ	±6%	10	100	kΩ	±5%
	Mechanical ringer test	Signal Frequency Range	10	80	Hz		10	80	Hz	
VPTL_TID_REN	Electronic ringer test	With 500 Ω to 7500 Ω series resistor and >100 k Ω parallel resistor (Note 3)	0	4	μF	±6% & ±50 nF	0	4	μF	±5% & ±50 nF

Table 15. Configuration C Measurement Range and Accuracy¹¹ (Continued)

				CONF	IGURATIO	N C		CONF	IGURATIO	N C							
				No	Calibratio	n		Facto	ry Calibra	tion							
				RSVA/RS	VB 0.5%, 1	00 ppm	RSVA/RSVB 0.5%, 100 ppm										
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification							
			1	1000	Ω	±4% & ±10 Ω	1	1000	Ω	±2.5% & ±10 Ω							
		Notes 3, 5, 8	1	10		±4% & ±10 Ω	1	10		±2.25% & ±10 Ω							
			10	30		±4.25%	10	30		±2.5%							
			30 100 kO	→ kO	-4.75%, +5.4%	30 100 kΩ	±2.5%										
	Resistance to GND		100	150	K22	-5.75%, +6.8%	100	150	K22	±2.5%							
			150	360		-10%, +14%	150	360		±3.35%							
			360	1000		-23%, +36%	360	1000	1	±7.5%							
			1	2		-65%, +100%	1	5		-21%, +34%							
							5	10	МΩ	-34%, +100%							
VPTL_TID_3ELE_RES,							10	20		-50%, infinity							
VPTL_TID_4ELE_RES					1	1000	Ω	±4% & ±20 Ω	1	1000	Ω	±2.5% & ±20 Ω					
									1	10		±4% & ±20 Ω	1	10		±2.25% & ±20 Ω	
																	10
			30	100	kΩ	±4.0%	30	100	kΩ	±2.5%							
	Resistance A to B	Notes 3, 5, 8	100	150	K22	±4.1%	100	150	KS2	±2.5%							
	Resistance A to b	140165 5, 5, 6	150	360	1	1 !			<u> </u>		±4.3%	150	360		±3.0%		
			360	1000		±6%	360	1000		±4.5%							
			1	5	ΜΩ	-20%, +40%	1	5		-15%, +20%							
			5	10	10122	-40%, +50%	5	10	МΩ	-25%, +40%							
		· ·					10	20	1	-40%, +120%							
VPTL_TID_3ELE_RES	Foreign DC currents	IAE + IBE (Notes 3, 8, 9)	0	80	mA	±5% & ±1.2 mA	0	80	mA	±4% & ±0.6 mA							
		AC current rejection	0	40	mArms	> 40 dB	0	40	mArms	> 40 dB							

Table 15. Configuration C Measurement Range and Accuracy¹¹ (Continued)

				CONF	GURATIC	ON C		CONF	IGURATIO	NC		
				No	Calibratio	n		Facto	ry Calibrat	ion		
				RSVA/RS\	/B 0.5%, 1	00 ppm	RSVA/RSVB 0.5%, 100 ppm					
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification		
			0	100	nF	±4.1% & ±0.55 nF	0	100	nF	±2.25% & ±0.3 nF		
	Capacitance to GND	Notes 3, 5, 8	100	1000	nF	±4.1% & ±1.0 nF	100	1000	nF	±2.25% & ±0.8 nF		
			1	20	μF	±4.45%	1	20	μF	±2.5%		
			20	50	μF	±5.2%	20	50	μF	±3.15%		
VPTL_TID_3ELE_CAP			0	100	nF	±4.1% & ±0.55 nF	0	100	nF	±2.25% & ±0.25 nF		
	Capacitance A to B	Notes 3, 5, 8	100	1000	nF	±4.15% & ±0.75 nF	100	1000	nF	±2.25% & ±0.65 nF		
			1	20	μF	±4.0%	1	20	μF	±2.4%		
			20	50	μF	±4.3%	20	50	μF	±2.6%		
		Signal Frequency Range	10	200	Hz		10	200	Hz			
VPTL_TID_FOREIGN_		IAE + IBE (Notes 3, 8, 9, 15)	0.1	50	mArms	±5% & ±0.01 mArms	0.1	50	mArms	±4% & ±0.01 mArms		
AC_CURRENT		Frequency Range	50	200	Hz		50	200	Hz			
		DC current rejection	-60	60	mA	> 40 dB	-60	60	mA	> 40 dB		
		Dial Speed	8	12	pps	±1.0%	8	12	pps	±1.0%		
	Dial pulse test	Break Interval	40	80	%	±1.0%	40	80	%	±1.0%		
	Diai puise test	Dial Speed	18	22	pps	±2.0%	18	22	pps	±2.0%		
		Break Interval	40	80	%	±2.0%	40	80	%	±2.0%		
VPTL_TID_DTMF_PULSE_ MSRMNT		DTMF Level (Notes 6, 8)	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB		
	DTMF test	DTMF Level (Notes 6, 8)	-25	-20	dBm	±1.5 dB	-25	-20	dBm	±1.5 dB		
		DTMF Frequency (Notes 6, 8)	600	2000	Hz	±2 Hz	600	2000	Hz	±2 Hz		

Table 15. Configuration C Measurement Range and Accuracy¹¹ (Continued)

			CONFIGURATION C				CONFIGURATION C							
				No Calibration				Facto	ry Calibra	tion				
				RSVA/RS\	/B 0.5%, 1	100 ppm	RSVA/RSVB 0.5%, 100 ppm							
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification				
			-40	0	dBm	±1 dB	-40	0	dBm	±1 dB				
VPTL_TID_NOISE		Notes 7, 8, 18, 20	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB				
			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB				
			-40	0	dBm	±1 dB	-40	0	dBm	±1 dB				
VPTL_TID_SNR_QNTZ_DIST		Notes 7, 8, 19	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB				
			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB				
VPTL_TID_ARB_TONE		Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB				
VITE_TID_ARB_TONE		140163 0, 0, 20	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz				
VPTL_TID_AC_TRANS		Notes 7, 8, 19	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB				
VI IL_IID_AO_INANO		140103 7, 0, 13	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz				
VPTL TID TONE GEN		Note 21	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB				
VI IE_IIB_IGNE_GEN		14010 21	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%				
VPTL TID UNBAL TONE	AC peak output	Notes 16, 17, 22	0	150	V	±2.4% & Note 16	0	150	V	±1.4% & Note 16				
VFTE_TID_GNBAE_TONE	Frequency output	Notes 10, 17, 22	10	1200	Hz	±2 Hz	10	1200	Hz	±2 Hz				
	DC level output		-150	150	V	±2.4% & ±0.7 V	-150	150	V	±1.4% & ±0.45 V				
VPTL_TID_DRAW_BREAK_	Self Test	Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB				
DIALTONE	OCII IESI	140.63 0, 0, 20	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz				
VPTL_TID_TRANS_HYBRID_		Notes 7 8 19	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB				
LOSS		Notes 7, 8, 19	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%				

Table 16. Configuration D Measurement Range and Accuracy¹¹

				CONI	FIGURA	TION D		CONF	IGURA	TION D		CONI	IGURA	TION D
				No	Calibra	tion		Facto	ry Calib	oration		In-Ser	vice Cal	ibration
			F		VB 0.5% alibration	, 100 ppm on Bus	F		VB 0.5% alibratio	n Bus	F		VB 0.5% ibration	6, 100 ppm Bus
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
			-1000	-400		±2.2% & ±3.0 V	-1000	-400		±1.95% & ±1.5 V	-1000	-400		±1.55% & ±0.7 V
VPTL_TID_OPEN_	Tip or ring	Notes 1, 3, 8, 10, 12, 13	-400	400	V	±1.9% & ±0.05 V	-400	400	V	±1.75% & ±0.05 V	-400	400	V	±1.1% & ±0.05 V
DC_VOLTAGE	voltage		400	1000		±2.2% & ±3.0 V	400	1000		±1.95% & ±1.5 V	400	1000		±1.55% & ±0.7 V
		AC induction rejection	0	280	Vrms	> 40 dB	0	280	Vrms	> 40 dB	0	280	Vrms	> 40 dB
		Notes 1, 3, 8, 10, 12, 14	0	280	Vrms	±1.9% & ±0.05 V	0	280	Vrms	±1.75% & ±0.05 V	0	280	Vrms	±1.1% & ±0.05 V
	Tip or ring	10, 12, 14	280	700		±2.2% & ±0.2 V	280	700		±1.95% & ±0.2 V	280	700		±1.55% & ±0.2 V
	voltage	Frequency Range	50	200	Hz		50	200	Hz		50	200	Hz	
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB	-400	400	V	> 40 dB
VPTL_TID_OPEN_ AC_VOLTAGE		Notes 1, 3, 8, 10, 12, 14	0	280	Vrms	±2.65% & ±0.05 V	0	280	Vrms	±1.8% & ±0.05 V	0	280	Vrms	±1.55% & ±0.05 V
		10, 12, 14	280	700		±3.1% & ±0.2 V	280	700		±2.5% & ±0.2 V	280	700		±2.2% & ±0.2 V
	Differential	Frequency Range	50	200	Hz		50	200	Hz		50	200	Hz	
	voltage	Common- mode Rejection	0	280	Vrms	< 2%	0	280	Vrms	< 2%	0	280	Vrms	< 2%
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB	-400	400	V	> 40 dB
VPTL_TID_	ILG current	Notes 2, 3, 8,	0	80	mA	±3.2% & ±0.02 mA	0	80	mA	±3.2% & ±0.02 mA	0	80	mA	±3.2% & ±0.02 mA
MONITOR_IV	IMT current	13, 14, 15	0	80	mA	±4.0% & ±0.02 mA	0	80	mA	±2.5% & ±0.02 mA	0	80	mA	±2.0% & ±0.02 mA
	Test with	Notes 2, 3, 8	0	4	kΩ	±6% & ±10 Ω	0	4	kΩ	±4.5% & ±10 Ω	0	4	kΩ	±3.5% & ±10 Ω
VPTL_TID_DC_ LOOP_RES	offset compensa- tion	Note 4	5	70	mA	±4.0% & ±2.0 mA	5	70	mA	±2.5% & ±0.75 mA	5	70	mA	±2.0% & ±0.5 mA

Table 16. Configuration D Measurement Range and Accuracy¹¹ (Continued)

										· ,				
				CONFI	GURAT	ION D		CONFI	GURAT	ION D		CONFI	GURAT	ION D
				No (Calibrat	ion		Factor	y Calib	ration		In-Servi	ce Calil	bration
			R		B 0.5%, libration	, 100 ppm n Bus	R		/B 0.5% libratio	, 100 ppm n Bus	R		B 0.5%	, 100 ppm Bus
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
		Notes 3, 8	1	10	kΩ	±5% & ±20 Ω	1	10	kΩ	±4.5% & ±20 Ω	1	10	kΩ	±3.5% & ±20 Ω
	Mechanical	Notes 3, 6	10	100	kΩ	±6%	10	100	kΩ	±5%	10	100	kΩ	±4%
	ringer test	Signal Freq. Range	10	80	Hz		10	80	Hz		10	80	Hz	
VPTL_TID_REN	Electronic ringer test	With 500 Ω to 7500 Ω series resistor and >100 k Ω parallel resistor (Note 3)	0	4	μF	±6% & ±50 nF	0	4	μF	±5% & ±50 nF	0	4	μF	±4% & ±50 nF
			1	1000	Ω	±4% &±10 Ω	1	1000	Ω	±2.5% & ±10 Ω	1	1000	Ω	±2.3% & ±7 Ω
			1	10		±4% & ±10 Ω	1	10		±2.25% & ±10 Ω	1	10		±1.85% & ±7 Ω
			10	30		±4.25%	10	30		±2.5%	10	30		±2.25%
	Resistance to		30	100	kΩ	±4.0%	30	100	kΩ	±2.5%	30	100	kΩ	±2.25%
	GND	Notes 3, 5, 8	100	150		±4.0%	100	150		±2.25%	100	150		±1.95%
			150	360		±4.15%	150	360		±2.5%	150	360		±2.2%
			360	1000		±5.1%	360	1000		±4.0%	360	1000		±3.65%
			1	5		-12%, +15%	1	5		-12%, +15%	1	5		-12%, +15%
VPTL_TID_			5	10	ΜΩ	-20%, +35%	5	10	МΩ	-20%, +35%	5	10	$M\Omega$	-20%, +35%
3ELE_RES,			10	20		-33%, +100%	10	20		-33%, +100%	10	20		-33%, +100%
VPTL_TID_ 4ELE_RES			1	1000	Ω	±4% & ±20 Ω	1	1000	Ω	±2.5% & ±20 Ω	1	1000	Ω	±2.3% & ±15 Ω
			1	10		±4% & ±20 Ω	1	10		±2.25% & ±20 Ω	1	10		±1.85% & ±15 Ω
			10	30		±4.35%	10	30		±2.5%	10	30		±2.25%
	Posiston as A to D	Noton 2 5 3	30	100	kΩ	±4.0%	30	100	kΩ	±2.5%	30	100	kΩ	±2.25%
	Resistance A to B Not	Notes 3, 5, 8	100	150		±4.0%	100	150		±2.25%	100	150		±1.95%
			150	360		±4.15%	150	360		±2.5%	150	360		±2.2%
			360	1000		±5.1%	360	1000		±4%	360	1000		±3.65%
			1	5		-12%, +15%	1	5		-12%, +15%	1	5		-12%, +15%
			5	10	МΩ	-20%, +35%	5	10	МΩ	-20%, +35%	5	10	$M\Omega$	-20%, +35%
			10	20		-33%, +100%	10	20		-33%, +100%	10	20		-33%, +100%

Table 16. Configuration D Measurement Range and Accuracy¹¹ (Continued)

				CONF	IGURAT	ION D		CONF	IGURAT	ION D		CONF	IGURAT	ION D
				No	Calibrat	ion		Factor	ry Calib	ration		In-Serv	ice Cali	bration
			R			100 ppm	R			, 100 ppm	R			, 100 ppm
		1		No Ca	libratio			No Ca	libratio			Cali	bration	
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
VPTL_TID_ 3ELE RES	Foreign DC currents	IAE + IBE (Notes 2, 3, 8, 9)	0	80	mA	±5% & ±0.02 mA	0	80	mA	±4% & ±0.02 mA	0	80	mA	±3% & ±0.02 mA
SEEL_NEO		AC current rejection	0	40	mA rms	> 40 dB	0	40	mA rms	> 40 dB	0	40	mA rms	> 40 dB
			0	100	nF	±4.1% & ±0.2 nF	0	100	nF	±2.25% & ±0.2 nF	0	100	nF	±1.9% & ±0.2 nF
	Capacitance to GND	Notes 3, 5, 8	100	1000	nF	±4.1% & ±0.9 nF	100	1000	nF	±2.25% & ±0.9 nF	100	1000	nF	±1.9% & ±0.9 nF
			1	20	μF	±4.45%	_1	20	μF	±2.4%	1	20	μF	±2.15%
			20	50	μF	±5.2%	20	50	μF	±3.15%	20	50	μF	±2.85%
VPTL_TID_ 3ELE_CAP			0	100	nF	±4.1% & ±0.25 nF	0	100	nF	±2.25% & ±0.2 nF	0	100	nF	±1.9% & ±0.2 nF
	Capacitance	Notes 3, 5, 8	100	1000	nF	±4.15% & ±1.1 nF	100	1000	nF	±2.25% & ±1.1 nF	100	1000	nF	±1.9% & ±1.1 nF
	A to B		1	20	μF	±4.0%	1	20	μF	±2.25%	1	20	μF	±1.9%
			20	50	μF	±4.3%	20	50	μF	±2.6%	20	50	μF	±2.3%
		Signal Freq. Range	10	200	Hz		10	200	Hz		10	200	Hz	
VPTL_TID_ FOREIGN		IAE + IBE (Notes 3, 8, 9,15)	0.1	50	mA rms	±5% & ±0.01 mArms	0.1	50	mA rms	±4% & ±0.01 mArms	0.1	50	mA rms	±3% & ±0.01 mArms
AC CURRENT		Freq. Range	50	200	Hz		50	200	Hz		50	200	Hz	
AO_OOKKEIVI		DC current rejection	-60	60	mA	> 40 dB	-60	60	mA	> 40 dB	-60	60	mA	> 40 dB
		Dial Speed	8	12	pps	±1.0%	8	12	pps	±1.0%	8	12	pps	±1.0%
	Dial pulse test	Break Interval	40	80	%	±1.0%	40	80	%	±1.0%	40	80	%	±1.0%
	Diai puise test	Dial Speed	18	22	pps	±2.0%	18	22	pps	±2.0%	18	22	pps	±2.0%
VPTL_TID_		Break Interval	40	80	%	±2.0%	40	80	%	±2.0%	40	80	%	±2.0%
	MF_PULSE_ SRMNT	DTMF Level	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB
MISKININI		(Notes 6, 8)	-25	-20	dBm	±1.5 dB	-25	-20	dBm	±1.5 dB	-25	-20	dBm	±1.5 dB
	DTMF test	DTMF Frequency (Notes 6, 8)	600	2000	Hz	±2 Hz	600	2000	Hz	±2 Hz	600	2000	Hz	±2 Hz

Table 16. Configuration D Measurement Range and Accuracy¹¹ (Continued)

				CONFI	GURAT	ION D		CONFI	GURAT	ION D		CONFI	GURAT	ON D
			No Calibration RSVA/RSVB 0.5%, 100 ppm					Factor	y Calibr	ration		In-Servi	ce Calik	ration
			R		B 0.5%, libration	• • •	R		/B 0.5%, libratior	100 ppm n Bus	R		B 0.5%, pration I	, 100 ppm Bus
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
		Notes 7 9 49	-40	0	dBm	±1 dB	-40	0	dBm	±1 dB	-40	0	dBm	±1 dB
VPTL_TID_NOISE		Notes 7, 8, 18, 20	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB
			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB
VPTL TID			-40	0	dBm	±1 dB	-40	0	dBm	±1 dB	-40	0	dBm	±1 dB
SNR QNTZ DIST		Notes 7, 8, 19	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB
01111_Q1112_D101			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB
VPTL_TID_		Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
ARB_TONE		140163 0, 0, 20	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz
VPTL_TID_		Notes 7, 8, 19	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB
AC_TRANS		140163 7, 0, 19	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz
VPTL_TID_		Note 21	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
TONE_GEN		Note 21	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%
VDTI TID	AC peak output	N	0	150	V	±2.4% & Note 16	0	150	V	±1.4% & Note 16	0	150	V	±1.3% & Note 16
VPTL_TID_ UNBAL TONE	Frequency output	Notes 16, 17, 22	10	1200	Hz	±2 Hz	10	1200	Hz	±2 Hz	10	1200	Hz	±2 Hz
ONBAL_TONE	DC level output		-150	150	V	±2.4% & ±0.7 V	-150	150	٧	±1.4% & ±0.45 V	-150	150	V	±1.3% & ±0.3 V
VPTL_TID_	Self Test	Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
DRAW_BREAK_	3011 103t	110103 3, 0, 20	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz
DIALTONE	Inward test	Notes 6, 8	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB
	iiiwaia tost	110.00 0, 0	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz
VPTL_TID_TRANS_ HYBRID_LOSS		Notes 7, 8, 19	-40 300	0 3400	dBm Hz	±1.0 dB	-40 300	0 3400	dBm Hz	±1.0 dB	-40 300	0 3400	dBm Hz	±1.0 dB
HYBRID_LOSS			300	3400	Hz	±0.25%	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%

CONFIGURATION E

Table 17. Configuration E Measurement Range and Accuracy¹¹
CONFIGURATION E

				No	Calibratio	n		Facto	ry Calibra	tion
				RSVA/RSV	/B 0.5%, 1	00 ppm		RSVA/RS\	/B 0.5%, 1	I00 ppm
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
			-1000	-400		±2.2% & ±3.0 V	-1000	-400		±1.95% & ±1.5 V
VPTL_TID_OPEN_DC_VOLTAGE	Tip or ring voltage	Notes 1, 3, 8, 10, 13	-400	400	V	±1.9% & ±1.0 V	-400	400	V	±1.75% & ±0.5 V
VI 12_118_01 2N_80_V021X02	Tip of fing voltage		400	1000		±2.2% & ±3.0 V	400	1000		±1.95% & ±1.5 V
		AC induction rejection	0	280	Vrms	> 40 dB	0	280	Vrms	> 40 dB
		Notes 1, 3, 8, 10, 14	0	280	Vrms	±1.9% & ±0.05 V	0	280	Vrms	±1.75% & ±0.05 V
	Tip or ring voltage		280	700		±2.2% & ±0.2 V	280	700		±1.95% & ±0.2 V
		Frequency Range	50	200	Hz		50	200	Hz	
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB
VPTL_TID_OPEN_AC_VOLTAGE		Notes 1, 3, 8, 10, 14	0	280	Vrms	±2.65% & ±0.05 V	0	280	Vrms	±1.8% & ±0.05 V
			280	700		±3.1% & ±0.2 V	280	700		±2.5% & ±0.2 V
	Differential voltage	Frequency Range	50	200	Hz		50	200	Hz	
		Common-mode Rejection	0	280	Vrms	< 2%	0	280	Vrms	< 2%
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB
VPTL TID MONITOR IV	ILG current	Notes 3, 8, 13, 14, 15	0	80	mA	±3.2% & ±1.0 mA	0	80	mA	±3.2% & ±1.0 mA
VI TE_TIB_IMONITON_IV	IMT current	1 10103 0, 0, 10, 14, 10	0	80	mA	±4.0% & ±1.0 mA	0	80	mA	±2.5% & ±0.75 mA
	Test with offset	Notes 2, 3, 8	0	4	kΩ	±6% & ±10 Ω	0	4	kΩ	±4.5% & ±10 Ω
VPTL_TID_DC_LOOP_RES	compensation	Note 4	5	70	mA	±4.0% & ±2.0 mA	5	70	mA	±2.5% & ±0.75 mA
		Notes 3, 8	1	10	kΩ	±5% & ±20 Ω	1	10	kΩ	±4.5% & ±20 Ω
	Mechanical ringer test		10	100	kΩ	±6%	10	100	kΩ	±5%
	mospanisa migar too.	Signal Frequency Range	10	80	Hz		10	80	Hz	
VPTL_TID_REN	Electronic ringer test	With 500 Ω to 7500 Ω series resistor and >100 k Ω parallel resistor (Note 3)	0	4	μF	±6% & ±50 nF	0	4	μF	±5% & ±50 nF

Table 17. Configuration E Measurement Range and Accuracy¹¹ (Continued)

				CONF	IGURATIO	N E		CONF	IGURATIO	ON E
				No	Calibratio	n		Factor	ry Calibra	tion
				RSVA/RS	/B 0.5%, 1	00 ppm		RSVA/RS\	/B 0.5%, 1	00 ppm
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
			1	10		±4% & ±10 Ω	1	10		±2.25% & ±10 Ω
			10	30		±4.25%	10	30		±2.5%
			30	100	kΩ	-4.75%, +5.4%	30	100	kΩ	±2.5%
			100	150	1 1/22	-5.75%, +6.8%	100	150	Na2	±2.5%
	Resistance to GND	Notes 3, 5, 8	150	360		-10%, +14%	150	360		±3.35%
			360	1000	ĺ (-23%, +36%	360	1000		±7.5%
			1	2	МΩ	-65%, +100%	1	5		-21%, +34%
							5	10	МΩ	-34%, +100%
VPTL_TID_3ELE_RES,							10	20		-50%, infinity
VPTL_TID_4ELE_RES			1	10		±4% & ±20 Ω	1	10		±2.25% & ±20 Ω
			10	30		±4.1%	10	30		±2.5%
			30	100	kΩ	±4.0%	30	100	kΩ	±2.5%
			100	150	KSZ	±4.1%	100	150	N22	±2.5%
	Resistance A to B	Notes 3, 5, 8	150	360		±4.3%	150	360		±3.0%
			360	1000		±6%	360	1000		±4.5%
			1	5	ΜΩ	-20%, +40%	1	5		-15%, +20%
			5	10	10122	-40%, +50%	5	10	МΩ	-25%, +40%
							10	20	1	-40%, +120%
VPTL_TID_3ELE_RES	Foreign DC currents	IAE + IBE (Notes 3, 8, 9)	0	80	mA	±5% & ±1.2 mA	0	80	mA	±4% & ±0.6 mA
		AC current rejection	0	40	mArms	> 40 dB	0	40	mArms	> 40 dB

Table 17. Configuration E Measurement Range and Accuracy¹¹ (Continued)

				CONF	IGURATIO	ON E		CONF	IGURATIO	NE
				No	Calibratio	n		Facto	ry Calibrat	ion
				RSVA/RS\	/B 0.5%, 1	I00 ppm		RSVA/RSV	/B 0.5%, 1	00 ppm
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
			0	100	nF	±4.1% & ±0.55 nF	0	100	nF	±2.25% & ±0.3 nF
	Capacitance to GND	Notes 3, 5, 8	100	1000	nF	±4.1% & ±1.0 nF	100	1000	nF	±2.25% & ±0.8 nF
			1	20	μF	±4.45%	1	20	μF	±2.5%
			20	50	μF	±5.2%	20	50	μF	±3.15%
VPTL_TID_3ELE_CAP			0	100	nF	±4.1% & ±0.55 nF	0	100	nF	±2.25% & ±0.25 nF
	Conscitones A to B	Notes 3, 5, 8	100	1000	nF	±4.15% & ±0.75 nF	100	1000	nF	±2.25% & ±0.65 nF
	Capacitance A to B		1	20	μF	±4.0%	1	20	μF	±2.4%
			20	50	μF	±4.3%	20	50	μF	±2.6%
		Signal Frequency Range	10	200	Hz		10	200	Hz	
VPTL_TID_FOREIGN_		IAE + IBE (Notes 3, 8, 9, 15)	0.1	50	mArms	±5% & ±0.01 mArms	0.1	50	mArms	±4% & ±0.01 mArms
AC_CURRENT		Frequency Range	50	200	Hz		50	200	Hz	
		DC current rejection	-60	60	mA	> 40 dB	-60	60	mA	> 40 dB
		Dial Speed	8	12	pps	±1.0%	8	12	pps	±1.0%
	Dial pulse test	Break Interval	40	80	%	±1.0%	40	80	%	±1.0%
	Diai puise test	Dial Speed	18	22	pps	±2.0%	18	22	pps	±2.0%
		Break Interval	40	80	%	±2.0%	40	80	%	±2.0%
VPTL_TID_DTMF_PULSE_ MSRMNT		DTMF Level (Notes 6, 8)	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB
	DTMF test	DTMF Level (Notes 6, 8)	-25	-20	dBm	±1.5 dB	-25	-20	dBm	±1.5 dB
		DTMF Frequency (Notes 6, 8)	600	2000	Hz	±2 Hz	600	2000	Hz	±2 Hz

Table 17. Configuration E Measurement Range and Accuracy¹¹ (Continued)

				CONF	GURATIC	ON E		CONF	IGURATIO	ON E
				No	Calibratio	n		Factor	ry Calibra	tion
				RSVA/RS\	/B 0.5%, 1	00 ppm		RSVA/RS\	/B 0.5%, 1	100 ppm
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
			-40	0	dBm	±1 dB	-40	0	dBm	±1 dB
VPTL_TID_NOISE		Notes 7, 8, 18, 20	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB
			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB
			-40	0	dBm	±1 dB	-40	0	dBm	±1 dB
VPTL_TID_SNR_QNTZ_DIST		Notes 7, 8, 19	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB
			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB
VPTL_TID_ARB_TONE		Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
VI TE_TID_AIRB_TOINE		140165 0, 0, 20	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz
VPTL TID AC TRANS		Notes 7, 8, 19	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB
VI IE_IID_AO_IIVANO		140103 7, 0, 13	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz
VPTL TID TONE GEN		Note 21	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
VI IE_IID_TONE_GEN		14010 21	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%
VPTL TID UNBAL TONE	AC peak output		0	150	٧	±2.4% & Note 16	0	150	V	±1.4% & Note 16
VPTL_TID_UNBAL_TONE	Frequency output	Notes 16, 17, 22	10	1200	Hz	±2 Hz	10	1200	Hz	±2 Hz
	DC level output		-150	150	V	±2.4% & ±0.7 V	-150	150	V	±1.4% & ±0.45 V
VPTL_TID_DRAW_BREAK_	Self Test	Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
DIALTONE	Jell lest	140165 0, 0, 20	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz
VPTL_TID_TRANS_HYBRID_		Notes 7, 8, 19	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB
LOSS		140165 7, 0, 19	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%

Table 18. Configuration F Measurement Range and Accuracy¹¹

				CON	FIGURA	TION F		CON	IGURA	TION F		CON	FIGURA	TION F
				No	Calibra	tion		Facto	ry Calib	oration		In-Ser	vice Cal	ibration
			F		VB 0.5% alibration	, 100 ppm on Bus	F		VB 0.5% alibratio	n Bus	F		VB 0.5% libration	6, 100 ppm Bus
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
			-1000	-400		±2.2% & ±3.0 V	-1000	-400		±1.95% & ±1.5 V	-1000	-400		±1.55% & ±0.7 V
VPTL_TID_OPEN_	Tip or ring	Notes 1, 3, 8, 10, 12, 13	-400	400	V	±1.9% & ±0.05 V	-400	400	V	±1.75% & ±0.05 V	-400	400	V	±1.1% & ±0.05 V
DC_VOLTAGE	voltage		400	1000		±2.2% & ±3.0 V	400	1000		±1.95% & ±1.5 V	400	1000		±1.55% & ±0.7 V
		AC induction rejection	0	280	Vrms	> 40 dB	0	280	Vrms	> 40 dB	0	280	Vrms	> 40 dB
		Notes 1, 3, 8, 10, 12, 14	0	280	Vrms	±1.9% & ±0.05 V	0	280	Vrms	±1.75% & ±0.05 V	0	280	Vrms	±1.1% & ±0.05 V
	Tip or ring	10, 12, 14	280	700		±2.2% & ±0.2 V	280	700		±1.95% & ±0.2 V	280	700		±1.55% & ±0.2 V
	voltage	Frequency Range	50	200	Hz		50	200	Hz		50	200	Hz	
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB	-400	400	V	> 40 dB
VPTL_TID_OPEN_ AC_VOLTAGE		Notes 1, 3, 8, 10, 12, 14	0	280	Vrms	±2.65% & ±0.05 V	0	280	Vrms	±1.8% & ±0.05 V	0	280	Vrms	±1.55% & ±0.05 V
		10, 12, 14	280	700		±3.1% & ±0.2 V	280	700		±2.5% & ±0.2 V	280	700		±2.2% & ±0.2 V
	Differential	Frequency Range	50	200	Hz		50	200	Hz		50	200	Hz	
	voltage	Common- mode Rejection	0	280	Vrms	< 2%	0	280	Vrms	< 2%	0	280	Vrms	< 2%
		Foreign DC rejection	-400	400	V	> 40 dB	-400	400	V	> 40 dB	-400	400	V	> 40 dB
VPTL_TID_	ILG current	Notes 2, 3, 8,	0	80	mA	±3.2% & ±0.02 mA	0	80	mA	±3.2% & ±0.02 mA	0	80	mA	±3.2% & ±0.02 mA
MONITOR_IV	IMT current	13, 14, 15	0	80	mA	±4.0% & ±0.02 mA	0	80	mA	±2.5% & ±0.02 mA	0	80	mA	±2.0% & ±0.02 mA
	Test with	Notes 2, 3, 8	0	4	kΩ	±6% & ±10 Ω	0	4	kΩ	±4.5% & ±10 Ω	0	4	kΩ	±3.5% & ±10 Ω
VPTL_TID_DC_ LOOP_RES	offset compensa- tion	Note 4	5	70	mA	±4.0% & ±2.0 mA	5	70	mA	±2.5% & ±0.75 mA	5	70	mA	±2.0% & ±0.5 mA

Table 18. Configuration F Measurement Range and Accuracy¹¹ (Continued)

				CONFI	GURAT	ION F		CONF	GURAT	ION F		CONFI	GURAT	ION F
				No (Calibrat	ion		Factor	y Calib	ration		In-Servi	ce Calik	oration
			R		B 0.5%, libration	100 ppm n Bus	R		B 0.5%	, 100 ppm n Bus	R		B 0.5%, oration I	100 ppm Bus
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
		Notes 3, 8	1	10	kΩ	±5% & ±20 Ω	1	10	kΩ	±4.5% & ±20 Ω	1	10	kΩ	±3.5% & ±20 Ω
	Mechanical	Notes 3, 8	10	100	kΩ	±6%	10	100	kΩ	±5%	10	100	kΩ	±4%
	ringer test	Signal Frequency Range	10	80	Hz		10	80	Hz		10	80	Hz	
VPTL_TID_REN	Electronic ringer test	With 500 Ω to 7500 Ω series resistor and >100 k Ω parallel resistor (Note 3)	0	4	μF	±6% & ±50 nF	0	4	μF	±5% & ±50 nF	0	4	μF	±4% & ±50 nF
			1	10		±4% & ±10 Ω	1	10		±2.25% & ±10 Ω	1	10		±1.85% & ±7 Ω
			10	30		±4.25%	10	30		±2.5%	10	30		±2.25%
			30	100	kΩ	±4.0%	30	100	kΩ	±2.5%	30	100	kΩ	±2.25%
	Resistance to	Notes 3, 5, 8	100	150		±4.0%	100	150		±2.25%	100	150		±1.95%
	GND	Notes 3, 5, 6	150	360		±4.15%	150	360		±2.5%	150	360		±2.2%
			360	1000		±5.1%	360	1000		±4.0%	360	1000		±3.65%
			1	5		-12%, +15%	1	5		-12%, +15%	1	5		-12%, +15%
VPTL_TID_			5	10	MΩ	-20%, +35%	5	10	MΩ	-20%, +35%	5	10	MΩ	-20%, +35%
3ELE_RES,		_	10	20		-33%, +100%	10	20		-33%, +100%	10	20		-33%, +100%
VPTL_TID_ 4ELE_RES			1	10		±4% & ±20 Ω	1	10		±2.25% & ±20 Ω	1	10		±1.85% & ±15 Ω
			10	30		±4.35%	10	30		±2.5%	10	30		±2.25%
	Resistance A to B		30	100	kΩ	±4.0%	30	100	kΩ	±2.5%	30	100	kΩ	±2.25%
		Notes 3, 5, 8	100	150		±4.0%	100	150		±2.25%	100	150		±1.95%
		110.00 0, 0, 0	150	360		±4.15%	150	360		±2.5%	150	360		±2.2%
			360	1000		±5.1%	360	1000		±4%	360	1000		±3.65%
			1	5	l vo	-12%, +15%	1	5		-12%, +15%	1	5	Ma	-12%, +15%
			5	10	ΜΩ	-20%, +35%	5	10	ΜΩ	-20%, +35%	5	10	MΩ	-20%, +35%
			10	20		-33%, +100%	10	20		-33%, +100%	10	20		-33%, +100%

Table 18. Configuration F Measurement Range and Accuracy¹¹ (Continued)

				CONF	IGURAT	ION F		CONF	IGURAT	TON F		CONF	IGURAT	ION F
				No	Calibrat	ion		Facto	ry Calib	ration		In-Serv	ice Cali	bration
			R		/B 0.5% llibratio	, 100 ppm n Bus	R		/B 0.5% libratio	, 100 ppm n Bus	R		/B 0.5% bration	, 100 ppm Bus
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
VPTL_TID_ 3ELE RES	Foreign DC currents	IAE + IBE (Notes 2, 3, 8, 9)	0	80	mA	±5% & ±0.02 mA	0	80	mA	±4% & ±0.02 mA	0	80	mA	±3% & ±0.02 mA
JLLL_NES	Currents	AC current rejection	0	40	mA rms	> 40 dB	0	40	mA rms	> 40 dB	0	40	mA rms	> 40 dB
			0	100	nF	±4.1% & ±0.2 nF	0	100	nF	±2.25% & ±0.2 nF	0	100	nF	±1.9% & ±0.2 nF
	Capacitance to GND	Notes 3, 5, 8	100	1000	nF	±4.1% & ±0.9 nF	100	1000	nF	±2.25% & ±0.9 nF	100	1000	nF	±1.9% & ±0.9 nF
			1	20	μF	±4.45%	1	20	μF	±2.4%	1	20	μF	±2.15%
			20	50	μF	±5.2%	20	50	μF	±3.15%	20	50	μF	±2.85%
VPTL_TID_ 3ELE_CAP			0	100	nF	±4.1% & ±0.25 nF	0	100	nF	±2.25% & ±0.2 nF	0	100	nF	±1.9% & ±0.2 nF
	Capacitance	Notes 3, 5, 8	100	1000	nF	±4.15% & ±1.1 nF	100	1000	nF	±2.25% & ±1.1 nF	100	1000	nF	±1.9% & ±1.1 nF
	A to B		1	20	μF	±4.0%	1	20	μF	±2.25%	1	20	μF	±1.9%
			20	50	μF	±4.3%	20	50	μF	±2.6%	20	50	μF	±2.3%
		Signal Freq. Range	10	200	Hz		10	200	Hz		10	200	Hz	
VPTL_TID_		IAE + IBE (Notes 3, 8, 9,15)	0.1	50	mA rms	±5% & ±0.01 mArms	0.1	50	mA rms	±4% & ±0.01 mArms	0.1	50	mA rms	±3% & ±0.01 mArms
FOREIGN_ AC_CURRENT		Freq. Range	50	200	Hz		50	200	Hz		50	200	Hz	
AC_CONNEIVI		DC current rejection	-60	60	mA	> 40 dB	-60	60	mA	> 40 dB	-60	60	mA	> 40 dB
		Dial Speed	8	12	pps	±1.0%	8	12	pps	±1.0%	8	12	pps	±1.0%
	Dial pulse test	Break Interval	40	80	%	±1.0%	40	80	%	±1.0%	40	80	%	±1.0%
	Diai paide toot	Dial Speed	18	22	pps	±2.0%	18	22	pps	±2.0%	18	22	pps	±2.0%
VPTL_TID_		Break Interval	40	80	%	±2.0%	40	80	%	±2.0%	40	80	%	±2.0%
DTMF_PULSE_ MSRMNT		DTMF Level	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB
INIOKININI		(Notes 6, 8)	-25	-20	dBm	±1.5 dB	-25	-20	dBm	±1.5 dB	-25	-20	dBm	±1.5 dB
	DTMF test	DTMF Frequency (Notes 6, 8)	600	2000	Hz	±2 Hz	600	2000	Hz	±2 Hz	600	2000	Hz	±2 Hz

Table 18. Configuration F Measurement Range and Accuracy¹¹ (Continued)

				CONF	GURAT	ION F		CONF	GURAT	ION F		CONFI	GURAT	ON F
				No (Calibrati	ion		Factor	y Calibr	ation		In-Servi	ce Calib	oration
			R		B 0.5%, libration	100 ppm n Bus	R		/B 0.5%, libratior	100 ppm n Bus	R		B 0.5%, pration I	, 100 ppm Bus
Test Library Function	Specific Test	Notes / Parameter	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification	From	То	Unit	Accuracy / Specification
		Notes 7 0 10	-40	0	dBm	±1 dB	-40	0	dBm	±1 dB	-40	0	dBm	±1 dB
VPTL_TID_NOISE		Notes 7, 8, 18, 20	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB
			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB
VPTL_TID_			-40	0	dBm	±1 dB	-40	0	dBm	±1 dB	-40	0	dBm	±1 dB
SNR QNTZ DIST		Notes 7, 8, 19	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB	-50	-40	dBm	±2 dB
ONN_QN12_DIOT			-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB	-60	-50	dBm	±3 dB
VPTL_TID_		Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
ARB_TONE		140103 0, 0, 20	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz
VPTL_TID_		Notes 7, 8, 19	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB	-40	0	dBm	±1.0 dB
AC_TRANS		140103 7, 0, 13	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz	300	3400	Hz	±2 Hz
VPTL_TID_		Note 21	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
TONE_GEN		14010 21	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%	300	3400	Hz	±0.25%
VDTI TID	AC peak output	No. 40 47	0	150	V	±2.4% & Note 16	0	150	٧	±1.4% & Note 16	0	150	V	±1.3% & Note 16
VPTL_TID_ UNBAL TONE	Frequency output	Notes 16, 17, 22	10	1200	Hz	±2 Hz	10	1200	Hz	±2 Hz	10	1200	Hz	±2 Hz
ONDAL_TONE	DC level output		-150	150	V	±2.4% & ±0.7 V	-150	150	٧	±1.4% & ±0.45 V	-150	150	V	±1.3% & ±0.3 V
VPTL_TID_	Self Test	Notes 6, 8, 20	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB	-40	0	dBm	±0.5 dB
DRAW BREAK	23/11/05/	110100 0, 0, 20	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz
DIALTONE	Inward test	Notes 6, 8	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB	-20	0	dBm	±1.0 dB
		110100 0, 0	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz	300	800	Hz	±2 Hz
VPTL_TID_TRANS_ HYBRID LOSS		Notes 7, 8, 19	-40 300	0 3400	dBm Hz	±1.0 dB ±0.25%	-40 300	0 3400	dBm Hz	±1.0 dB ±0.25%	-40 300	0 3400	dBm Hz	±1.0 dB ±0.25%
TTDND_LOSS			300	3400	112	±0.25/0	300	3400	112	±0.20/0	300	3400	112	±0.25/0

Notes:

- 1. The total voltage range is ±1000 V for the sum of AC and DC signals and may be further limited by the protection devices.
- 2. Using the two-step method with offset cancellation
- 3. Absolute and relative tolerances are additive.
- 4. The achievable current will be limited by the driver output voltage as a function of the load under test.
- 5. Accuracies only apply to a real resistor or to a real capacitor of the exact value of the test load. Resistance and Capacitance measurement accuracies are given for a single element present. The presence of an impedance in any of the other two branches may cause >50 times this impedance to appear in the branch under test and will degrade the observed accuracy. This is also true for the branches that are open. When performing the 3 element measurement the test will measure all 3 branches, whether the branches are open or not.
- 6. Accuracies are given for FFT sizes of 1024 or more.
- 7. Accuracies are given for filter integration time of 100 ms or more.
- 8. Accuracies are given for testing in the absence of interference from a foreign AC or DC voltage.
- 9. The total current range is ± 80 mA for the sum of the AC and DC signals.
- 10. The specified tolerance for RSVA and RSVB is ±0.5% with a temperature coefficient of resistance of 100 ppm/°C. Stated performance is only validated and guaranteed for the 0.5%, 100 ppm/°C resistor. If a looser tolerance resistor is used, DC voltage and AC voltage measurement accuracies need to be relaxed. For instance, if a resistor with a ±1% tolerance and a 200 ppm/°C temperature coefficient of resistance is used, then widen the accuracies as follows. For No Calibration tests, widen the listed VPTL_TID_OPEN_DC_VOLTAGE and VPTL_TID_OPEN_AC_VOLTAGE accuracies by 0.2%. For Factory Calibration and In-Service Calibration tests, widen the listed VPTL_TID_OPEN_DC_VOLTAGE and VPTL_TID_OPEN_AC_VOLTAGE accuracies by 0.25%. If non-standard configurations are used, customer must do due diligence with regards to validation.
- 11. Additional notes with regards to stated accuracies: Accuracies are set at 99% of the estimated distribution including all BOM component tolerances as documented in the NGCC Hardware Design Guide, Doc ID 126583. Tolerance for any overcurrent protection PTC component is ±10%. Calibration circuit has tolerances and temperature coefficients as specified in the Calibration Circuit Parts List. Temperature at Factory Calibration time is 20°C ±10°C. The temperature changes by no more than 20°C between executing the SLAC internal calibration function, executing In-Service Calibration (if applicable), applying the Factory or In-Service calibration factors (if applicable), and running the test.
- 12. Accuracy of VPTL_TID_INWRD_CUR is set by this test.
- 13. Accuracy of DC voltage level when using VPTL_TID_MONITOR_IV is set by VPTL_TID_OPEN_DC_VOLTAGE.
- 14. Accuracy of AC voltage level when using VPTL_TID_MONITOR_IV is set by VPTL_TID_OPEN_AC_VOLTAGE.
- 15. Accuracy of AC current level when using VPTL_TID_MONITOR_IV is set by VPTL_TID_FOREIGN_AC_CURRENT.
- 16. AC amplitude accuracy:

Maximum percentage increase = 100% *
$$\sqrt{\frac{1 + \left(\frac{\text{freq}}{3617}\right)^2}{1 + \left(\frac{\text{freq}}{5741}\right)^2}} - 1$$

Maximum percentage decrease = 100% *
$$\sqrt{\frac{1 + \left(\frac{\text{freq}}{3617}\right)^2}{1 + \left(\frac{\text{freq}}{2529}\right)^2}} - 1$$

- 17. Level is limited by the selection of power supply rails.
- 18. Accuracy figures are given for a measurement of wideband noise applied to the Tip and Ring port and measured with any of the optional noise filters. The accuracy figure relates the rms noise result produced by the line test with the rms noise result produced by a reference instrument using the same filter selection and the same input impedance.
- 19. The accuracy figures provide the tolerances to be applied to the sum of the nominal transmit path and receive path frequency response computed by WinSLAC for the AC profile and the load impedance used during the test.
- 20. The accuracy figures provide the tolerances to be applied to the nominal transmit path frequency response computed by WinSLAC for the AC profile and the signal source impedance used during the test.

- 21. The accuracy figures provide the tolerances to be applied to the nominal receive path frequency response computed by WinSLAC for the AC profile and the load impedance used during the test.
- 22. The maximum peak-to-peak signal amplitude is reduced as the frequency increases because the maximum rate of change must be limited to 250 V/ms on the Tip and Ring port when using 220 nF C_{DCA} and C_{DCB} capacitors. This is equivalent to a 11.7 Vpeak sinewave at 3400 Hz.

Calibration Circuit

The calibration circuit used for In-Service Calibration is shown in <u>Figure 7</u>. The circuit provides a precision reference voltage and precision reference loads. The Test-In Bus leads are wired to the Calibration Bus leads of Configuration D as shown in <u>Figure 3</u> or Configuration F as shown in <u>Figure 6</u>. The relays are controlled by the host controller.

The bill of materials for the calibration circuit is listed in <u>Table 19</u>.

Figure 7. Calibration Circuit

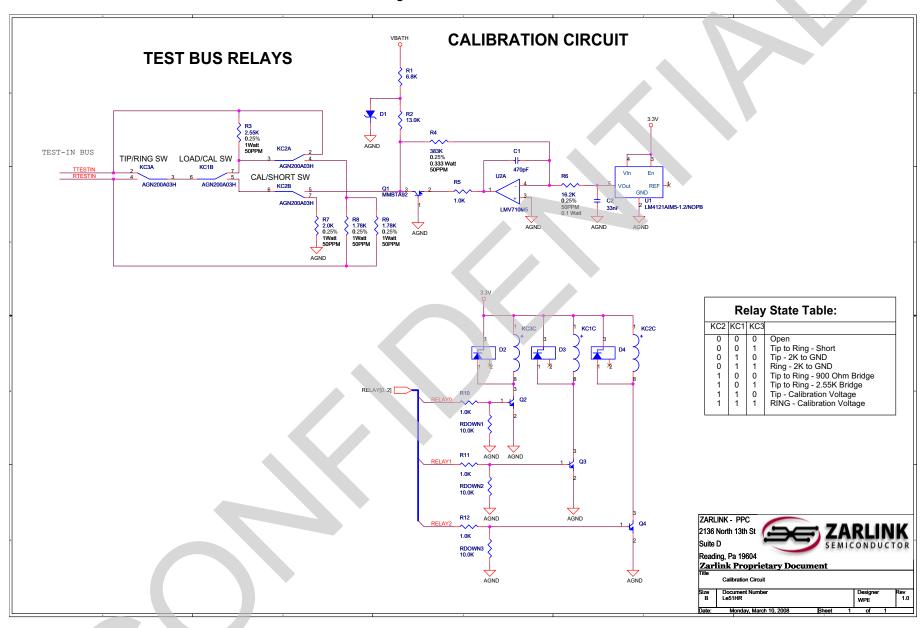


Table 19. Calibration Circuit Parts List

Item	Туре	Part Number	Manufacturer	Value	Required Tolerance	Rating	T.C.R.
U1	Voltage Reference	LM4121AIM5-1.2	National Semiconductor		±0.2%		50 ppm
U2A	Op Amp	LMV710M5	National Semiconductor			Max offset ±3 mV	
Q1	Transistor	MMBTA92	Diodes Inc.	500 mA		300 V	
Q2, Q3, Q4	NPN Transistor	MMBT3904T	Diodes Inc.	200 mA		40 V	
R1	Resistor	ERJ-1TYJ682U	Panasonic	6.8 kΩ	±5%	1 W	
R2	Resistor	ERJ-6ENF1302V	Panasonic	13 kΩ	±1%	1/10 W	
R3	Resistor	PTN2512H2551BS	Vishay	2.55 kΩ	±0.25%	1 W	50 ppm
R4	Resistor	TNPW1206383KBHTYEA	Vishay	383 kΩ	±0.25%	1/3 W	50 ppm
R5, R10, R11, R12	Resistor	ERJ-2RKF1001X	Panasonic	1.0 kΩ	±10%	1/16 W	
R6	Resistor	TNPW060316K2BHENEA	Vishay	16.2 kΩ	±0.25%		50 ppm
R7	Resistor	PTN2512H2001BS	Vishay	2.0 kΩ	±0.25%	1 W	50 ppm
R8, R9	Resistor	PTN2512H1781BS	Vishay	1.78 kΩ	±0.25%	1 W	50 ppm
C1	Capacitor	C0402C471K5RACTU	Kemet	470 pF	±10%	50 V	
C2	Capacitor	C0402C103K4RACTU	Kemet	33 nF	±10%	50 V	
D1	Zener Diode	1SMA5941	Taiwan Semiconductor	47 V		1.5 W	
D2, D3, D4	Diode	BAS116T	Diodes Inc.			85 V	
KC1C, KC2C, KC3C	DPDT Relay	AGN200A03	Aromat			3 V	

Note:

Listed part numbers may have a tighter tolerance then required.

Termination and Signature Network Diagrams

Figure 8. M-Socket Termination

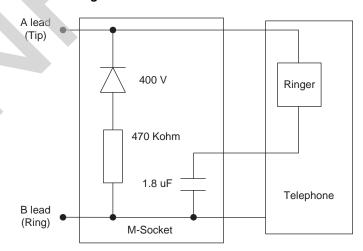


Figure 9. PPA Termination

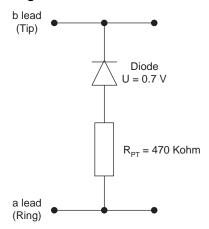


Figure 10. IAD Signature Networks

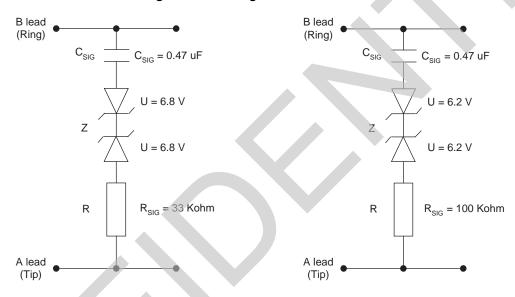


Figure 11. CPE Splitter Signature Network

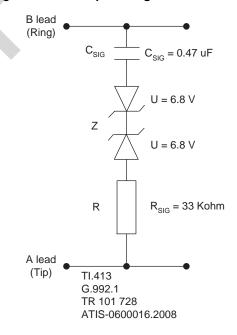


Figure 12. CO Splitter Signature Networks

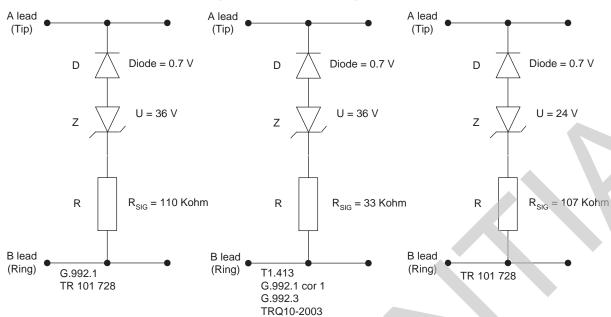
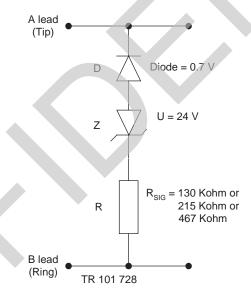


Figure 13. ETSI CPE Signature Network



MEMORY REQUIREMENTS

Refer to VCP2-792 Memory Requirements Worksheet, Document ID #142757, to calculate estimated memory requirements for a specific application.

CHANGE SUMMARY

Version 2 to Version 3

- Added VP_TERM_RR_MW termination type.
- Changed Ringing Bus Relay state in Figure 4 and Figure 6 to normally open.
- Added Repetitive AC Transmission Test.
- Enhanced Extended Group Test and Fast Group Test descriptions.
- Overhauled notes in Tables 13 through 16.
- Removed Inward Test from VPTL_TID_DRAW_BREAK_DIAL_TONE for Configuration C and E.
- Updated Figure 9.

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